XLF232-512-FB374 Datasheet

Document Number: X008766,



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1 xCORE Multicore Microcontrollers

The xCORE200 Series is a comprehensive range of 32-bit multicore microcontrollers that brings the low latency and timing determinism of the xCORE architecture to mainstream embedded applications. Unlike conventional microcontrollers, xCORE multicore microcontrollers execute multiple real-time tasks simultaneously and communicate between tasks using a high speed network. Because xCORE multicore microcontrollers are completely deterministic, you can write software to implement functions that traditionally require dedicated hardware.

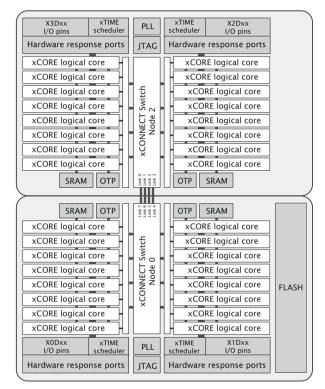


Figure 1: XLF232-512-FB374 block diagram

Key features of the XLF232-512-FB374 include:

- ► **Tiles**: Devices consist of one or more xCORE tiles. Each tile contains between five and eight 32-bit xCOREs with highly integrated I/O and on-chip memory.
- Logical cores Each logical core can execute tasks such as computational code, DSP code, control software (including logic decisions and executing a state machine) or software that handles I/O. Section 6.1
- xTIME scheduler The xTIME scheduler performs functions similar to an RTOS, in hardware. It services and synchronizes events in a core, so there is no requirement for interrupt handler routines. The xTIME scheduler triggers cores

on events generated by hardware resources such as the I/O pins, communication channels and timers. Once triggered, a core runs independently and concurrently to other cores, until it pauses to wait for more events. Section 6.2

- Channels and channel ends Tasks running on logical cores communicate using channels formed between two channel ends. Data can be passed synchronously or asynchronously between the channel ends assigned to the communicating tasks. Section 6.5
- xCONNECT Switch and Links Between tiles, channel communications are implemented over a high performance network of xCONNECT Links and routed through a hardware xCONNECT Switch. Section 6.6
- ▶ **Ports** The I/O pins are connected to the processing cores by Hardware Response ports. The port logic can drive its pins high and low, or it can sample the value on its pins optionally waiting for a particular condition. Section 6.3
- Clock blocks xCORE devices include a set of programmable clock blocks that can be used to govern the rate at which ports execute. Section 6.4
- Memory Each xCORE Tile integrates a bank of SRAM for instructions and data, and a block of one-time programmable (OTP) memory that can be configured for system wide security features. Section 9
- PLL The PLL is used to create a high-speed processor clock given a low speed external oscillator. Section 7
- ▶ Flash The device has a built-in 2MBflash. Section 8
- ▶ JTAG The JTAG module can be used for loading programs, boundary scan testing, in-circuit source-level debugging and programming the OTP memory. Section 10

1.1 Software

Devices are programmed using C, C++ or xC (C with multicore extensions). XMOS provides tested and proven software libraries, which allow you to quickly add interface and processor functionality such as USB, Ethernet, PWM, graphics driver, and audio EQ to your applications.

1.2 xTIMEcomposer Studio

The xTIMEcomposer Studio development environment provides all the tools you need to write and debug your programs, profile your application, and write images into flash memory or OTP memory on the device. Because xCORE devices operate deterministically, they can be simulated like hardware within xTIMEcomposer: uniquely in the embedded world, xTIMEcomposer Studio therefore includes a static timing analyzer, cycle-accurate simulator, and high-speed in-circuit instrumentation.

xTIMEcomposer can be driven from either a graphical development environment, or the command line. The tools are supported on Windows, Linux and MacOS X

and available at no cost from xmos.com/downloads. Information on using the tools is provided in the xTIMEcomposer User Guide, X3766.



2 XLF232-512-FB374 Features

► Multicore Microcontroller with Advanced Multi-Core RISC Architecture

- 32 real-time logical cores on 4 xCORE tiles
- Cores share up to 2000 MIPS
 - Up to 4000 MIPS in dual issue mode
- Each logical core has:
 - Guaranteed throughput of between 1/5 and 1/8 of tile MIPS
 - 16x32bit dedicated registers
- 167 high-density 16/32-bit instructions
 - All have single clock-cycle execution (except for divide)
 - 32x32 ${\rightarrow}64$ bit MAC instructions for DSP, arithmetic and user-definable cryptographic functions

► Programmable I/O

- 256 general-purpose I/O pins, configurable as input or output
 - Up to 56 x 1bit port, 22 x 4bit port, 13 x 8bit port, 6 x 16bit port, 4 x 32bit port
 8 xCONNECT links
- Port sampling rates of up to 60 MHz with respect to an external clock
- 128 channel ends (32 per tile) for communication with other cores, on or off-chip

Memory

- 512KB internal single-cycle SRAM (max 128KB per tile) for code and data storage
- 32KB internal OTP (max 8KB per tile) for application boot code
- 2MB internal flash for application code and overlays

Hardware resources

- 24 clock blocks (6 per tile)
- 40 timers (10 per tile)
- 16 locks (4 per tile)
- ► JTAG Module for On-Chip Debug

Security Features

• Programming lock disables debug and prevents read-back of memory contents

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• AES bootloader ensures secrecy of IP held on external flash memory

• Ambient Temperature Range

- Commercial qualification: 0°C to 70°C
- Industrial qualification: -40 °C to 85 °C
- Speed Grade
 - 40: 2000 MIPS
- Power Consumption
 - 1140 mA (typical)
- ▶ 374-pin FBGA package 0.8 mm pitch

3 Pin Configuration

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21
A	GND	VDDIO	X1D11	X1D32	X1D26	VDDIOT	X1D41	X0D31	X0D29	ты	VDDIO	CLK	TDO	X3D32	X3D30	VDDIOT	X2D31	X2D29	X2D32	VDDIO	GND
В	X0D37 X,c;	X0D36	X1D10	X1D33	X1027	X1D42	X1D40	X0D30	X0D28	X2D36	GND	RST_N	тск	X3D33	X3D31	X3D27	X2D30	X2D28	X2D27 X/27	X2D26 X(2)	11. X2D35 X,27
с	X0D39 X(C)	X0D38 X0238	VDD	X1D30	X1D28	x1D43	GND	X0D33	X0D32	MODE1	OTP VCC	TRST_	X3D10	X3D29	GND	x3D43	x3D41	X2D33	VDD	X2D25	X2D34 X;17
D	X0D41 X(L)	X0D40 X ₁ L ₁	X1D34 X,C;	X1D31	X1D29	GND	VDDIO	NC	DEBUG_ N	MODE0		TMS	X3D11	x3D28	X3D26	x3D42	X3D40	22A X2D70 X ₁ L ²¹	X3D00 X(1)	10 X3D01 X,47	и Х2D24 _{Х,1} 7
E	X0D43 X0T	00 X0D42 X,42	X1D35 X,02	VDD	VDD	GND	VDDIO	VDD	VDD				VDD	VDD	VDDIO	GND	VDD	VDD	22A X2D69 X,22	3008 X3D08 X,L?	X3D09 X,L?
F	X1D36	VDDIO	GND	VDD	VDD	VDD	VDD	VDD	VDD	PLL AGND	PLL AVDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	GND	VDDIO	200A X2D68 X ₃ L ² ₆
G	X1D49	X1D50 X(1);	X1D51 X,1,7	NC	NC	NC	NC	NC	NC				NC	NC	NC	NC	NC	NG	22A X2D67 X,JC	22A X2D66 X ₂ C ⁴	220A X2D65 X_jL_1^2
н	X1D53 X,L ²	X1D52 X,L;	VDD																VDD	228A X2D63 X,4,5	$\overset{223}{\underset{X_{i}L_{n}^{2}}{\overset{223}}}$
J	22A X1D54 X,12	22A X1D55 X,17	VDD		GND	GND	GND	GND	GND				GND	GND	GND	GND	GND		VDD	22A X2D62 X,42	220A X2D61 X_12
к	X1D58	X1D57 X157	X1D56		GND	GND	GND	GND	GND				GND	GND	GND	GND	GND		22A X2D56 ×,z;	22A X2D57 X ₂ P ₁ ²⁵	200A X2D58 X_{2}^{10}
L	VDDIO	GND	X1D61		GND	GND	GND	GND	GND				GND	GND	GND	GND	GND		22A X2D55 ×,z;	GND	VDDIO
м	X1D64 X,12	X1D63 X,12	X1D62 X,L2		GND	GND	GND	GND	GND				GND	GND	GND	GND	GND		22A X2D54 X,C?	22A X2D53 X42	200A X2D52 X(1)
N	X1D65 X,17	X1D66 X,12	VDD		GND	GND	GND	GND	GND				GND	GND	GND	GND	GND		VDD	X2D50 ×,c?	200A X2D51 X_12
Р	X1D68	X1D67 X_127	VDD																VDD	X3D06 X;p;	X3D07 X ₃ L ⁴⁰
R	X1D69 X,12	X1D70 X(L) ^{20A}	X1D37 ×,1.5	NG	NC	NC	NG	NG	NC				NC	NC	NG	NC	NC	NG	X2D49 X3L1	X3D04 X(F)	40 X3D05 ×,↓,
т	X1D38 X,12	VDDIO	GND	VDD	VDD	VDD	VDD	VDD	VDD	VDD	GND	VDD	VDD	VDD	VDD	VDD	VDD	VDD	GND	VDDIO	48. X3D03 X ₁ 2 ⁴
U	X1017	Х1 <mark>0</mark> 16 ҚС	X1039 X123	VDD	VDD	GND	VDDIO	NC	VDD		VDDIO		VDD	VDD	VDDIO	GND	VDD	VDD	NC	X2D19	X3D02 X ₃ L ⁰
v	X1D19	X1D18 X121	X0D01 X ₁ C ²	X0D02	X0D08	X0D11	NC	X1D14	и Х1D25	X0D21	NG	X3D23	x2D05	X2D07	NC	NC	x3D15	X3D21	X2D12	X2D17 X(2)	X2D18 ×j. ²
w	X0D10 X,c1	X1D22 X ₁ C ^{1G}	VDD33	X0D03	X0D09	NC	GND	X1D15	X0D14	X0D12	X0D23	X2D00	x2D04	X2D06	GND	NC	X3D14	X3D20	VDD33	X2D23	X2D16 ×,L;
Y	X1D23	X0D00	X0D04	X0D06	X1D12	NC	X1D24	X1D20	X0D15	X0D13	GND	X2D11	X2D02	X2D08	X3D13	NC	X2D14	X2D20	X3D24	× X2D13	X2D22
AA	GND	VDDIO	X0D05	X0D07	x1D13	NC	NC	X1D21	X0D20	X0D22	VDDIO	X3D12	X2D03	X2D09	NC	NC	40 X2D15	x2D21	X3D25	VDDIO	GND

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4 Signal Description

This section lists the signals and I/O pins available on the XLF232-512-FB374. The device provides a combination of 1 bit, 4bit, 8bit and 16bit ports, as well as wider ports that are fully or partially (gray) bonded out. All pins of a port provide either output or input, but signals in different directions cannot be mapped onto the same port.

Pins may have one or more of the following properties:

- PD/PU: The IO pin has a weak pull-down or pull-up resistor. On GPIO pins this resistor can be enabled. This resistor is designed to ensure defined logic input state for unconnected pins. It should not be used to pull external circuitry. Note that the resistors are highly non-linear and only a maximum pull current is specified in Section 12.2.
- ST: The IO pin has a Schmitt Trigger on its input.
- ▶ IOT: The IO pin is powered from VDDIOT (X1) or VDDIOT_2 (X3), not VDDIO
- ▶ IO: the pin is powered from VDDIO

Power pins (9)									
Signal	Function	Туре	Properties						
GND	Digital ground	GND							
OTP_VCC	OTP power supply	PWR							
PLL_AGND	Analog ground for PLL	PWR							
PLL_AVDD	Analog PLL power	PWR							
VDD	Digital tile power	PWR							
VDD33	Peripheral power	PWR							
VDDIO	Digital I/O power	PWR							
VDDIOT	Digital I/O power (top)	PWR							
VDDIOT_2	Digital I/O power (top, X3)	PWR							

	JTAG pins (6)		
Signal	Function	Туре	Properties
RST_N	Global reset input	Input	IO, PU, ST
тск	Test clock	Input	IO, PD, ST
TDI	Test data input	Input	IO, PU
TDO	Test data output	Output	IO, PD
TMS	Test mode select	Input	IO, PU
TRST_N	Test reset input	Input	IO, PU, ST

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			1/0) pins	(176)			
Signal	Function						Туре	Properties
X0D00		1A ⁰					I/0	IO, PD
X0D01	X ₀ L3 ² _{out}	1 B ⁰					I/0—	IO, PD
X0D02			4A ⁰	8A ⁰	16A ⁰	32A ²⁰	I/0	IO, PD
X0D03			4A ¹	8A ¹	16A ¹	32A ²¹	I/O	IO, PD
X0D04			4B ⁰	8A ²	16A ²	32A ²²	I/0—	IO, PD
X0D05			4B ¹	8A ³	16A ³	32A ²³	I/0—	IO, PD
X0D06			4B ²	8A ⁴	16A ⁴	32A ²⁴	I/0—	IO, PD
X0D07			4B ³	8A ⁵	16A ⁵	32A ²⁵	I/0—	IO, PD
X0D08			4A ²	8A ⁶	16A ⁶	32A ²⁶	I/O	IO, PD
X0D09			4A ³	8A ⁷	16A ⁷	32A ²⁷	I/O	IO, PD
X0D10	X ₀ L3 ³ _{out}	1C ⁰					I/0—	IO, PD
X0D11		1D ⁰					I/O	IO, PD
X0D12		1 E ⁰					I/O	IO, PD
X0D13		1 F ⁰					I/O	IO, PD
X0D14			4C ⁰	8B ⁰	16A ⁸	32A ²⁸	I/O	IO, PD
X0D15			4C ¹	8B1	16A ⁹	32A ²⁹	I/0	IO, PD
X0D20			4C ²	8B ⁶	16A ¹⁴	32A ³⁰	I/O	IO, PD
X0D21			4C ³	8B ⁷	16A ¹⁵	32A ³¹	I/O	IO, PD
X0D22		1G ⁰					I/O	IO, PD
X0D23		1H ⁰					I/O	IO, PD
X0D28			4F ⁰	8C ²	16B ²		I/O	IO, PD
X0D29			4F ¹	8C ³	16B ³		I/O	IO, PD
X0D30			4F ²	8C ⁴	16B ⁴		I/O	IO, PD
X0D31			4F ³	8C ⁵	16B ⁵		I/O	IO, PD
X0D32			4E ²	8C ⁶	16B ⁶		I/O	IO, PD
X0D33			4E ³	8C ⁷	16B ⁷		I/0	IO, PD
X0D36		1M ⁰		8D ⁰	16B ⁸		I/0	IO, PD
X0D37	X ₀ L0 ⁴ _{in}	1 N ⁰		8D ¹	16B ⁹		I/O	IO, PD
X0D38	X ₀ L0 ³ _{in}	10 ⁰		8D ²	16B ¹⁰		I/O	IO, PD
X0D39	X ₀ L0 ² _{in}	1 P ⁰		8D ³	16B ¹¹		I/O	IO, PD
X0D40	X ₀ L0 ¹ _{in}			8D ⁴	16B ¹²		I/O	IO, PD
X0D41	X ₀ L0 ⁰ _{in}			8D ⁵	16B ¹³		I/O	IO, PD
X0D42	X ₀ L0 ⁰ _{out}			8D ⁶	16B ¹⁴		I/O	IO, PD
X0D43	X ₀ L0 ¹ _{out}			8D ⁷	16B ¹⁵		I/O	IO, PD
X1D10		1C ⁰					I/O	IOT, PD
X1D11		1D ⁰					I/O	IOT, PD
X1D12		1 E ⁰					I/O	IO, PD
X1D13		1 F ⁰					I/O	IO, PD
X1D14			4C ⁰	8B ⁰	16A ⁸	32A ²⁸	I/O	IO, PD
X1D15			4C ¹	8B1	16A ⁹	32A ²⁹	I/O	IO, PD
X1D16	X ₀ L3 ¹ _{in}		4D ⁰	8B ²	16A ¹⁰		I/O	IO, PD
								(continued)

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Signal	Function					Туре	Properties
X1D17	X ₀ L3 ⁰ _{in}	4D ¹	8B ³	16A ¹¹		1/0	IO, PD
X1D18	X ₀ L3 ⁰ _{out}	4D ²	8B ⁴	16A ¹²		I/O	IO, PD
X1D19	X ₀ L3 ¹ _{out}	4D ³	8B ⁵	16A ¹³		I/O	IO, PD
X1D20		4C ²	8B ⁶	16A ¹⁴	32A ³⁰	I/O	IO, PD
X1D21		4C ³	8B ⁷	16A ¹⁵	32A ³¹	I/O	IO, PD
X1D22	X ₀ L3 ⁴ 1G		05		527	I/O	IO, PD
X1D23	14					I/O	IO, PD
X1D24	110					I/O	IO, PD
X1D25	1J ^C					I/O	IO, PD
X1D26	.,	4E ⁰	8C ⁰	16B ⁰		I/O	IOT, PD
X1D27		4E ¹	8C ¹	16B ¹		I/O	IOT, PD
X1D28		4F ⁰	8C ²	16B ²		I/O	IOT, PD
X1D29		4F ¹	8C ³	16B ³		I/O	IOT, PD
X1D30		4F ²	8C ⁴	16B ⁴		I/O	IOT, PD
X1D31		4F ³	8C ⁵	16B ⁵		I/O	IOT, PD
X1D32		4E ²	8C ⁶	16B ⁶		1/0	IOT, PD
X1D33		4E ³	8C ⁷	16B ⁷		I/O	IOT, PD
X1D34	X ₀ L0 ² 1K					I/O	IO, PD
X1D35	$X_0L0_{out}^3$ 1L					I/O	IO, PD
X1D36	X ₀ L0 ⁴ _{out} 1N		8D ⁰	168 ⁸		1/0	IO, PD
X1D37	$X_0L3_{in}^4$ 1N		8D ¹	16B ⁹		1/0	IO, PD
X1D38	$X_0 L3_{in}^3$ 10		8D ²	16B ¹⁰		1/0	IO, PD
X1D39	$X_0L3_{in}^2$ 1P		8D ³	16B ¹¹		1/0	IO, PD
X1D30	Nuclo _{in} II		8D ⁴	16B ¹²		I/O	IOT, PD
X1D41			8D ⁵	16B ¹³		I/O	IOT, PD
X1D42			8D ⁶	16B ¹⁴		1/0	IOT, PD
X1D43			8D ⁷	16B ¹⁵		1/0	IOT, PD
X1D49	X ₀ L1 ⁴		00	105	32A ⁰	I/O	IO, PD
X1D50	X ₀ L1 ³				32A ¹	I/O	IO, PD
X1D51	$X_0L1_{in}^2$				32A ²	I/O	IO, PD
X1D52	$X_0L1_{in}^1$				32A ³	I/O	IO, PD
X1D53	X ₀ L1 ⁰				32A ⁴	I/O	IO, PD
X1D54	X ₀ L1 ⁰ _{out}				32A ⁵	1/0	IO, PD
X1D55	X ₀ L1 ¹				32A ⁶	I/O	IO, PD
X1D56	X ₀ L1 ² X ₀ L1 ²				32A ⁷	I/O	IO, PD
X1D57	X ₀ L1 ³ _{out}				32A ⁸	I/O	IO, PD
X1D58	X ₀ L1 ⁴				32A ⁹	I/O	IO, PD
X1D61	$X_0L_{in}^4$				32A ¹⁰	1/0	IO, PD
X1D62	$X_0L2_{in}^3$				32A ¹¹	1/0	IO, PD
X1D63	$X_0L2_{in}^2$				32A ¹²	I/O	IO, PD
X1D64	$X_0L2_{in}^1$				32A ¹³	1/0	IO, PD
X1D65	$X_0L2_{in}^0$ $X_0L2_{in}^0$				32A ¹⁴	1/0	IO, PD
X1D66	$X_0L2_{in}^0$ $X_0L2_{out}^0$				32A ¹⁵	I/O	IO, PD
A1D00	∧0Ľ∠out				JZA -	1/0	(continued)

(continued)

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Signal	Function						Туре	Properties
X1D67	X ₀ L2 ¹ ut					32A ¹⁶	I/O	IO, PD
X1D68	X ₀ L2 ² _{out}					32A ¹⁷	I/O	IO, PD
X1D69	X ₀ L2 ³ _{out}					32A ¹⁸	I/O	IO, PD
X1D70	$X_0L2_{out}^4$					32A ¹⁹	I/O	IO, PD
X2D00		1A ⁰					I/O	IO, PD
X2D02			4A ⁰	8A ⁰	16A ⁰	32A ²⁰	I/O	IO, PD
X2D03			4A ¹	8A1	16A ¹	32A ²¹	I/O	IO, PD
X2D04			4B ⁰	8A ²	16A ²	32A ²²	I/O	IO, PD
X2D05			4B ¹	8A ³	16A ³	32A ²³	I/O	IO, PD
X2D06			4B ²	8A ⁴	16A ⁴	32A ²⁴	I/O	IO, PD
X2D07			4B ³	8A ⁵	16A ⁵	32A ²⁵	I/O	IO, PD
X2D08			4A ²	8A ⁶	16A ⁶	32A ²⁶	I/O	IO, PD
X2D09			4A ³	8A ⁷	16A ⁷	32A ²⁷	I/O	IO, PD
X2D11		1D ⁰					I/O	IO, PD
X2D12		1 E ⁰					I/O	IO, PD
X2D13		1 F ⁰					I/0	IO, PD
X2D14			4C ⁰	8B ⁰	16A ⁸	32A ²⁸	I/O	IO, PD
X2D15			4C ¹	8B1	16A ⁹	32A ²⁹	I/0	IO, PD
X2D16	X ₂ L4 ⁴ _{in}		4D ⁰	8B ²	16A ¹⁰		I/0	IO, PD
X2D17	X ₂ L4 ³ _{in}		4D ¹	8B ³	16A ¹¹		I/O	IO, PD
X2D18	X ₂ L4 ²		4D ²	8B ⁴	16A ¹²		I/O	IO, PD
X2D19	X ₂ L4 ¹		4D ³	8B ⁵	16A ¹³		I/O	IO, PD
X2D20			4C ²	8B ⁶	16A ¹⁴	32A ³⁰	I/O	IO, PD
X2D21			4C ³	8B ⁷	16A ¹⁵	32A ³¹	I/0	IO, PD
X2D22		1G ⁰					I/0	IO, PD
X2D23		1H ⁰					I/O	IO, PD
X2D24	X ₂ L7 ⁰	110					I/O	IO, PD
X2D25	X ₂ L7 ⁰ _{out}	1J ⁰					I/O	IO, PD
X2D26	$X_2L7_{out}^3$		4E ⁰	8C ⁰	16B ⁰		I/0	IO, PD
X2D27	X ₂ L7 ⁴ _{out}		4E ¹	8C ¹	16B ¹		I/0	IO, PD
X2D28			4F ⁰	8C ²	16B ²		I/O	IO, PD
X2D29			4F ¹	8C ³	16B ³		I/O	IO, PD
X2D30			4F ²	8C ⁴	16B ⁴		I/O	IO, PD
X2D31			4F ³	8C ⁵	16B ⁵		I/O	IO, PD
X2D32			4E ²	8C ⁶	16B ⁶		I/O	IO, PD
X2D33			4E ³	8C ⁷	16B ⁷		I/O	IO, PD
X2D34	X ₂ L7 ¹ ut	1K ⁰					I/O	IO, PD
X2D35	X ₂ L7 ² _{out}	1L ⁰					I/O	IO, PD
X2D36		1 M ⁰		8D ⁰	16B ⁸		I/0	IO, PD
X2D49	X ₂ L5 ⁴ _{in}					32A ⁰	I/O	IO, PD
X2D50	X ₂ L5 ³ _{in}					32A ¹	I/O	IO, PD
X2D51	X ₂ L5 ² _{in}					32A ²	I/O	IO, PD
X2D52	X ₂ L5 ¹ _{in}					32A ³	I/O	IO, PD
-	4 ⁻ 11							(continued)

-XMOS"-	-X	M	O	S°-
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(continued)

X2DS3 $\chi_2 L_{9}^{kn}$ $32A^4$ I/O IO, PD X2DS4 $\chi_2 L_{9}^{kn}$ $32A^5$ I/O IO, PD X2DS5 $\chi_2 L_{9}^{kn}$ $32A^6$ I/O IO, PD X2DS5 $\chi_2 L_{9}^{kn}$ $32A^7$ I/O IO, PD X2DS7 $\chi_2 L_{9}^{kn}$ $32A^7$ I/O IO, PD X2DS8 $\chi_2 L_{9}^{kn}$ $32A^7$ I/O IO, PD X2DS1 $\chi_2 L_{9}^{kn}$ $32A^{11}$ I/O IO, PD X2DS2 $\chi_2 L_{9}^{kn}$ $32A^{11}$ I/O IO, PD X2DS3 $\chi_2 L_{9}^{kn}$ $32A^{11}$ I/O IO, PD X2DS4 $\chi_2 L_{9}^{kn}$ $32A^{15}$ I/O IO, PD X2DS5 $\chi_2 L_{9}^{kn}$ $32A^{15}$ I/O IO, PD X2DS6 $\chi_2 L_{9}^{kn}$ $32A^{12}$ I/O IO, PD X2DS6 $\chi_2 L_{9}^{kn}$ $32A^{12}$ I/O IO, PD X3D00 $\chi_2 L_{9}^{kn}$ $32A^{2}$ I/O <t< th=""><th>Signal</th><th>Function</th><th></th><th></th><th></th><th></th><th>Туре</th><th>Properties</th></t<>	Signal	Function					Туре	Properties
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X2D53	$X_2L5_{in}^0$				32A ⁴	I/0	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X2D54	X ₂ L5 ⁰ _{out}				32A ⁵	I/0	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X2D55	X ₂ L5 ¹ _{out}				32A ⁶	I/0	IO, PD
X2D58 $X_2L5_{out}^4$ $32A^9$ I/O IO, PD X2D61 $X_2L6_m^4$ $32A^{10}$ I/O IO, PD X2D62 $X_2L6_m^4$ $32A^{11}$ I/O IO, PD X2D63 $X_2L6_m^4$ $32A^{12}$ I/O IO, PD X2D64 $X_2L6_m^4$ $32A^{12}$ I/O IO, PD X2D65 $X_2L6_m^6$ $32A^{12}$ I/O IO, PD X2D66 $X_2L6_m^6$ $32A^{15}$ I/O IO, PD X2D67 $X_2L6_m^6$ $32A^{16}$ I/O IO, PD X2D68 $X_2L6_m^6$ $32A^{18}$ I/O IO, PD X2D69 $X_2L6_m^6$ $32A^{19}$ I/O IO, PD X3D00 $X_2L7_m^2$ $1A^0$ I/O IO, PD X3D01 $X_2L4_m^6$ $4A^0$ $8A^0$ $16A^0$ $32A^{21}$ I/O IO, PD X3D02 $X_2L4_m^6$ $4A^0$ $8A^0$ $16A^0$ $32A^{22}$ I/O IO, PD X3D03 $X_2L4_m^6$ $4A^0$ $8A^0$ $16A^0$ $32A^{23}$	X2D56	X ₂ L5 ² _{out}				32A ⁷	I/O	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X2D57	X ₂ L5 ³ _{out}				32A ⁸	I/0	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X2D58	X ₂ L5 ⁴ _{out}				32A ⁹	I/0	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X2D61	X ₂ L6 ⁴ _{in}				32A ¹⁰	I/0	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X2D62	X ₂ L6 ³ _{in}				32A ¹¹	I/0	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X2D63	X ₂ L6 ² _{in}				32A ¹²	I/0	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X2D64	X ₂ L6 ¹ _{in}					I/0	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X2D65	X ₂ L6 ⁰ _{in}				32A ¹⁴	I/O	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X2D66	X ₂ L6 ⁰ _{out}				32A ¹⁵	I/0	IO, PD
X2D69 $X_2L6_{out}^2$ $32A^{18}$ I/O IO PD X2D70 $X_2L6_{out}^2$ $32A^{19}$ I/O IO, PD X3D00 $X_2L7_{in}^2$ $1A^0$ I/O IO, PD X3D01 $X_2L7_{in}^2$ $1A^0$ I/O IO, PD X3D02 $X_2L4_{in}^0$ $4A^0$ $8A^0$ $16A^0$ $32A^{20}$ I/O IO, PD X3D03 $X_2L4_{out}^2$ $4A^0$ $8A^0$ $16A^0$ $32A^{20}$ I/O IO, PD X3D04 $X_2L4_{out}^2$ $4A^1$ $8A^1$ $16A^3$ $32A^{22}$ I/O IO, PD X3D04 $X_2L4_{out}^2$ $4B^0$ $8A^2$ $16A^2$ $32A^{23}$ I/O IO, PD X3D05 $X_2L4_{out}^2$ $4B^0$ $8A^2$ $16A^2$ $32A^{24}$ I/O IO, PD X3D05 $X_2L4_{out}^2$ $4B^0$ $8A^2$ $16A^2$ $32A^{27}$ I/O IO, PD X3D07 $X_2L4_{out}^4$ $4B^3$ $8A^5$ $16A^6$ $32A^{27}$ I/O IO, PD X3D08 $X_$	X2D67	X ₂ L6 ¹ _{out}				32A ¹⁶	I/O	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X2D68	X ₂ L6 ² _{out}				32A ¹⁷	I/O	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X2D69	X ₂ L6 ³ _{out}				32A ¹⁸	I/0	IO, PD
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	X2D70	X ₂ L6 ⁴ _{out}				32A ¹⁹	I/0	IO, PD
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	X3D00	X ₂ L7 ² 1A ⁰					I/0	IO, PD
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	X3D01						I/0	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X3D02		4A ⁰	8A ⁰	16A ⁰	32A ²⁰	I/0	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X3D03		4A ¹	8A ¹	16A ¹	32A ²¹	I/0	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X3D04		4B ⁰	8A ²	16A ²	32A ²²	I/0	IO, PD
X3D06 $X_2L4_{0ut}^3$ $4B^2$ $8A^4$ $16A^4$ $32A^{24}$ I/O IO, PD X3D07 $X_2L4_{0ut}^4$ $4B^3$ $8A^5$ $16A^5$ $32A^{25}$ I/O IO, PD X3D08 $X_2L7_{in}^4$ $4A^2$ $8A^6$ $16A^6$ $32A^{26}$ I/O IO, PD X3D09 $X_2L7_{in}^3$ $4A^3$ $8A^7$ $16A^7$ $32A^{27}$ I/O IO, PD X3D10 $1C^0$ I/O IO, PD I/O IO, PD X3D11 $1D^0$ I/O IO, PD I/O IO, PD X3D12 $1E^0$ I/O IO, PD X3D13 $1F^0$ I/O IO, PD X3D14 $4C^0$ $8B^0$ $16A^8$ $32A^{28}$ I/O IO, PD X3D20 $4C^2$ $8B^6$ $16A^{14}$ $32A^{30}$ I/O IO, PD X3D21 $4C^3$ $8B^7$ $16A^{15}$ $32A^{21}$ I/O IO, PD X3D23 $1H^0$ I/O IO, PD I/O IO, PD X3D24 $1I^0$ I/O IO, PD I/O IO, PD X3D25 $1J^0$ I/O IO, PD I/O IO, PD X3D26 $4E^0$ $8C^0$ $16B^0$ I/O IO, PD X3D28 $4F^0$ $8C^2$ $16B^3$ I/O IOT, PD X3D29 $4F^1$ $8C^3$ $16B^3$ I/O IOT, PD X3D30 $4F^2$ $8C^4$ $16B^4$ I/O IOT, PD	X3D05		4B ¹	8A ³	16A ³	32A ²³	I/0	IO, PD
X3D07 $X_2L4_{out}^4$ $4B^3$ $8A^5$ $16A^5$ $32A^{25}$ I/O IO, PD X3D08 $X_2L7_{in}^4$ $4A^2$ $8A^6$ $16A^6$ $32A^{26}$ I/O IO, PD X3D09 $X_2L7_{in}^3$ $4A^3$ $8A^7$ $16A^7$ $32A^{27}$ I/O IO, PD X3D10 $1C^0$ I/O IOT, PD X3D11 $1D^0$ I/O IOT, PD X3D12 $1E^0$ I/O IO, PD X3D13 $1F^0$ I/O IO, PD X3D14 $4C^0$ $8B^0$ $16A^8$ $32A^{28}$ I/O X3D15 $4C^1$ $8B^1$ $16A^9$ $32A^{29}$ I/O IO, PD X3D20 $4C^2$ $8B^6$ $16A^{14}$ $32A^{30}$ I/O IO, PD X3D23 $1H^0$ I/O IO, PD I/O IO, PD X3D24 $1I^0$ I/O IO, PD I/O IO, PD X3D25 $1J^0$ I/O IO, PD I/O IO, PD X3D26 $4E^0$ $8C^0$ $16B^0$ I/O IOT, PD X3D28 $4F^0$ $8C^2$ $16B^2$ I/O IOT, PD X3D29 $4F^1$ $8C^3$ $16B^3$ I/O IOT, PD X3D30 $4F^2$ $8C^4$ $16B^4$ I/O IOT, PD	X3D06		4B ²	8A ⁴	16A ⁴	32A ²⁴	I/0	IO, PD
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	X3D07		4B ³	8A ⁵	16A ⁵	32A ²⁵	I/0	IO, PD
X3D10 $1C^0$ $1/O$ IOT, PDX3D11 $1D^0$ $1/O$ IOT, PDX3D12 $1E^0$ $1/O$ IO, PDX3D13 $1F^0$ $1/O$ IO, PDX3D14 $4C^0$ $8B^0$ $16A^8$ $32A^{28}$ $1/O$ X3D15 $4C^1$ $8B^1$ $16A^9$ $32A^{29}$ $1/O$ IO, PDX3D20 $4C^2$ $8B^6$ $16A^{14}$ $32A^{30}$ $1/O$ IO, PDX3D21 $4C^3$ $8B^7$ $16A^{15}$ $32A^{31}$ $1/O$ IO, PDX3D23 $1H^0$ $1/O$ IO, PDX3D24 110^0 $1/O$ IO, PDX3D26 $4E^0$ $8C^0$ $16B^0$ $1/O$ IOT, PDX3D28 $4F^0$ $8C^2$ $16B^2$ $1/O$ IOT, PDX3D29 $4F^1$ $8C^3$ $16B^3$ $1/O$ IOT, PDX3D30 $4F^2$ $8C^4$ $16B^4$ $1/O$ IOT, PD	X3D08	X ₂ L7 ⁴	4A ²	8A ⁶	16A ⁶	32A ²⁶	I/O	IO, PD
X3D10 $1C^0$ I/OIOT, PDX3D11 $1D^0$ I/OIOT, PDX3D12 $1E^0$ I/OIO, PDX3D13 $1F^0$ I/OIO, PDX3D14 $4C^0$ $8B^0$ $16A^8$ $32A^{28}$ I/OX3D15 $4C^1$ $8B^1$ $16A^9$ $32A^{29}$ I/OIO, PDX3D20 $4C^2$ $8B^6$ $16A^{14}$ $32A^{30}$ I/OIO, PDX3D21 $4C^3$ $8B^7$ $16A^{15}$ $32A^{31}$ I/OIO, PDX3D23 $1H^0$ I/OIO, PDX3D24 $1I^0$ I/OIO, PDX3D26 $4E^0$ $8C^0$ $16B^0$ I/OIOT, PDX3D27 $4E^1$ $8C^1$ $16B^1$ I/OIOT, PDX3D29 $4F^1$ $8C^3$ $16B^3$ I/OIOT, PDX3D30 $4F^2$ $8C^4$ $16B^4$ I/OIOT, PD	X3D09	X ₂ L7 ³	4A ³	8A ⁷	16A ⁷	32A ²⁷	I/O	IO, PD
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	X3D10						I/O	IOT, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X3D11	1D ⁰					I/O	IOT, PD
X3D14 $4C^0 8B^0 16A^8 32A^{28}$ I/OIO, PDX3D15 $4C^1 8B^1 16A^9 32A^{29}$ I/OIO, PDX3D20 $4C^2 8B^6 16A^{14} 32A^{30}$ I/OIO, PDX3D21 $4C^3 8B^7 16A^{15} 32A^{31}$ I/OIO, PDX3D23 $1H^0$ I/OIO, PDX3D24 $1I^0$ I/OIO, PDX3D25 $1J^0$ I/OIO, PDX3D26 $4E^0 8C^0 16B^0$ I/OIOT, PDX3D27 $4E^1 8C^1 16B^1$ I/OIOT, PDX3D28 $4F^0 8C^2 16B^2$ I/OIOT, PDX3D29 $4F^1 8C^3 16B^3$ I/OIOT, PDX3D30 $4F^2 8C^4 16B^4$ I/OIOT, PD	X3D12	1 E ⁰					I/0	IO, PD
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	X3D13	1 F ⁰					I/0	IO, PD
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	X3D14		4C ⁰	8B ⁰	16A ⁸	32A ²⁸	I/O	IO, PD
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	X3D15		4C ¹	8B1	16A ⁹	32A ²⁹	I/0	IO, PD
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	X3D20		4C ²	8B ⁶	16A ¹⁴	32A ³⁰	I/O	IO, PD
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	X3D21		4C ³	8B ⁷	16A ¹⁵	32A ³¹	I/0	IO, PD
X3D25 $1J^0$ I/O IO, PD X3D26 $4E^0$ $8C^0$ $16B^0$ I/O IOT, PD X3D27 $4E^1$ $8C^1$ $16B^1$ I/O IOT, PD X3D28 $4F^0$ $8C^2$ $16B^2$ I/O IOT, PD X3D29 $4F^1$ $8C^3$ $16B^3$ I/O IOT, PD X3D30 $4F^2$ $8C^4$ $16B^4$ I/O IOT, PD	X3D23	1H ⁰					I/0	IO, PD
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	X3D24	11 ⁰					I/O	IO, PD
X3D27 4E ¹ 8C ¹ 16B ¹ I/O IOT, PD X3D28 4F ⁰ 8C ² 16B ² I/O IOT, PD X3D29 4F ¹ 8C ³ 16B ³ I/O IOT, PD X3D30 4F ² 8C ⁴ 16B ⁴ I/O IOT, PD	X3D25	1J ⁰					I/O	IO, PD
X3D28 4F ⁰ 8C ² 16B ² I/O IOT, PD X3D29 4F ¹ 8C ³ 16B ³ I/O IOT, PD X3D30 4F ² 8C ⁴ 16B ⁴ I/O IOT, PD	X3D26		4E ⁰	8C ⁰	16B ⁰		I/O	IOT, PD
X3D29 4F ¹ 8C ³ 16B ³ I/O IOT, PD X3D30 4F ² 8C ⁴ 16B ⁴ I/O IOT, PD	X3D27		4E ¹	8C ¹	16B ¹		I/O	IOT, PD
X3D30 4F ² 8C ⁴ 16B ⁴ I/O IOT, PD	X3D28		4F ⁰	8C ²	16B ²		I/O	IOT, PD
	X3D29		4F ¹	8C ³	16B ³		I/O	IOT, PD
X3D31 4F ³ 8C ⁵ 16B ⁵ I/O IOT, PD	X3D30		4F ²	8C ⁴	16B ⁴		I/O	IOT, PD
	X3D31		4F ³	8C ⁵	16B ⁵		I/0	IOT, PD

XLF232-512-FB374 Datasheet

Signal	Function	Туре	Properties
X3D32	4E ² 8C ⁶ 16B ⁶	I/0	IOT, PD
X3D33	4E ³ 8C ⁷ 16B ⁷	I/O	IOT, PD
X3D40	8D ⁴ 16B ¹²	I/O	IOT, PD
X3D41	8D ⁵ 16B ¹³	I/O	IOT, PD
X3D42	8D ⁶ 16B ¹⁴	I/O	IOT, PD
X3D43	8D ⁷ 16B ¹⁵	I/O	IOT, PD

System pins (4)									
Signal	Function	Туре	Properties						
CLK	PLL reference clock	Input	IO, PD, ST						
DEBUG_N	Multi-chip debug	I/O	IO, PU						
MODE0	Boot mode select	Input	PU						
MODE1	Boot mode select	Input	PU						



5 Example Application Diagram

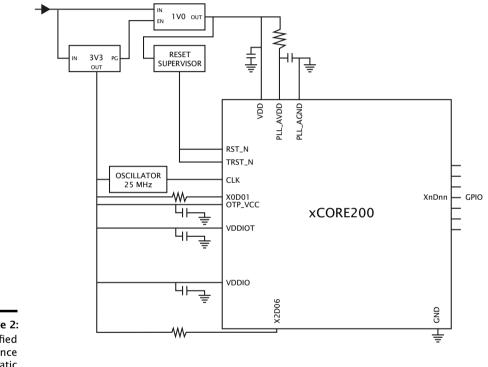


Figure 2: Simplified Reference Schematic

▶ see Section 11 for details on the power supplies and PCB design

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6 Product Overview

The XLF232-512-FB374 is a powerful device that consists of four xCORE Tiles, each comprising a flexible logical processing cores with tightly integrated I/O and on-chip memory.

6.1 Logical cores

Each tile has 8 active logical cores, which issue instructions down a shared fivestage pipeline. Instructions from the active cores are issued round-robin. If up to five logical cores are active, each core is allocated a fifth of the processing cycles. If more than five logical cores are active, each core is allocated at least 1/n cycles (for *n* cores). Figure 3 shows the guaranteed core performance depending on the number of cores used.

Figure 3: Logical core performance

gure 3:	Speed	MIPS	Frequency		Minim	um MIF	'S per c	ore (fo	r n co	res)	
al core	grade			1	2	3	4	5	6	7	8
mance	20	2000 MIPS	500 MHz	100	100	100	100	100	83	71	63

There is no way that the performance of a logical core can be reduced below these predicted levels (unless *priority threads* are used: in this case the guaranteed minimum performance is computed based on the number of priority threads as defined in the architecture manual). Because cores may be delayed on I/O, however, their unused processing cycles can be taken by other cores. This means that for more than five logical cores, the performance of each core is often higher than the predicted minimum but cannot be guaranteed.

The logical cores are triggered by events instead of interrupts and run to completion. A logical core can be paused to wait for an event.

6.2 xTIME scheduler

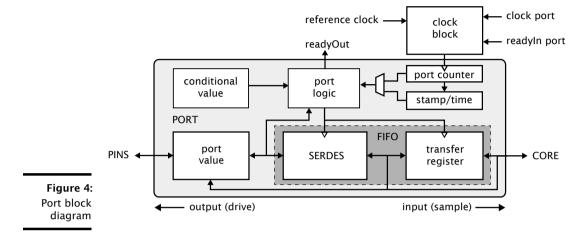
The xTIME scheduler handles the events generated by xCORE Tile resources, such as channel ends, timers and I/O pins. It ensures that all events are serviced and synchronized, without the need for an RTOS. Events that occur at the I/O pins are handled by the Hardware-Response ports and fed directly to the appropriate xCORE Tile. An xCORE Tile can also choose to wait for a specified time to elapse, or for data to become available on a channel.

Tasks do not need to be prioritised as each of them runs on their own logical xCORE. It is possible to share a set of low priority tasks on a single core using cooperative multitasking.

6.3 Hardware Response Ports

Hardware Response ports connect an xCORE tile to one or more physical pins and as such define the interface between hardware attached to the XLF232-512-FB374, and the software running on it. A combination of 1 bit, 4 bit, 8 bit, 16 bit and 32 bit

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ports are available. All pins of a port provide either output or input. Signals in different directions cannot be mapped onto the same port.

The port logic can drive its pins high or low, or it can sample the value on its pins, optionally waiting for a particular condition. Ports are accessed using dedicated instructions that are executed in a single processor cycle. xCORE-200 IO pins can be used as *open collector* outputs, where signals are driven low if a zero is output, but left high impedance if a one is output. This option is set on a per-port basis.

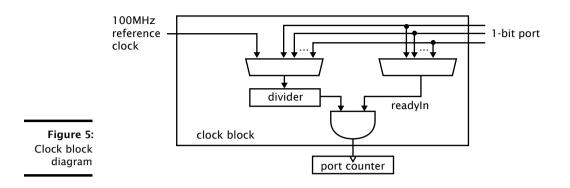
Data is transferred between the pins and core using a FIFO that comprises a SERDES and transfer register, providing options for serialization and buffered data.

Each port has a 16-bit counter that can be used to control the time at which data is transferred between the port value and transfer register. The counter values can be obtained at any time to find out when data was obtained, or used to delay I/O until some time in the future. The port counter value is automatically saved as a timestamp, that can be used to provide precise control of response times.

The ports and xCONNECT links are multiplexed onto the physical pins. If an xConnect Link is enabled, the pins of the underlying ports are disabled. If a port is enabled, it overrules ports with higher widths that share the same pins. The pins on the wider port that are not shared remain available for use when the narrower port is enabled. Ports always operate at their specified width, even if they share pins with another port.

6.4 Clock blocks

xCORE devices include a set of programmable clocks called clock blocks that can be used to govern the rate at which ports execute. Each xCORE tile has six clock blocks: the first clock block provides the tile reference clock and runs at a default frequency of 100MHz; the remaining clock blocks can be set to run at different frequencies.



A clock block can use a 1-bit port as its clock source allowing external application clocks to be used to drive the input and output interfaces. xCORE-200 clock blocks optionally divide the clock input from a 1-bit port.

In many cases I/O signals are accompanied by strobing signals. The xCORE ports can input and interpret strobe (known as readyIn and readyOut) signals generated by external sources, and ports can generate strobe signals to accompany output data.

On reset, each port is connected to clock block 0, which runs from the xCORE Tile reference clock.

6.5 Channels and Channel Ends

Logical cores communicate using point-to-point connections, formed between two channel ends. A channel-end is a resource on an xCORE tile, that is allocated by the program. Each channel-end has a unique system-wide identifier that comprises a unique number and their tile identifier. Data is transmitted to a channel-end by an output-instruction; and the other side executes an input-instruction. Data can be passed synchronously or asynchronously between the channel ends.

6.6 xCONNECT Switch and Links

XMOS devices provide a scalable architecture, where multiple xCORE devices can be connected together to form one system. Each xCORE device has an xCONNECT interconnect that provides a communication infrastructure for all tasks that run on the various xCORE tiles on the system.

The interconnect relies on a collection of switches and XMOS links. Each xCORE device has an on-chip switch that can set up circuits or route data. The switches are connected by xConnect Links. An XMOS link provides a physical connection between two switches. The switch has a routing algorithm that supports many different topologies, including lines, meshes, trees, and hypercubes.

The links operate in either 2 wires per direction or 5 wires per direction mode, depending on the amount of bandwidth required. Circuit switched, streaming

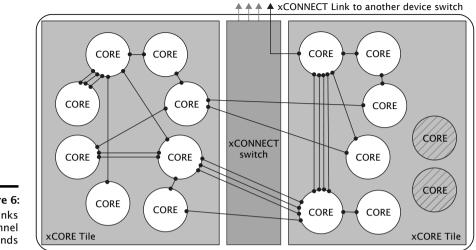


Figure 6: Switch, links and channel ends

and packet switched data can both be supported efficiently. Streams provide the fastest possible data rates between xCORE Tiles (up to 250 MBit/s), but each stream requires a single link to be reserved between switches on two tiles. All packet communications can be multiplexed onto a single link.

Information on the supported routing topologies that can be used to connect multiple devices together can be found in the XS1-LF Link Performance and Design Guide, X2999.

7 PLL

The PLL creates a high-speed clock that is used for the switch, tile, and reference clock. The PLL multiplication value is selected through the two MODE pins, and can be changed by software to speed up the tile or use less power. The MODE pins are set as shown in Figure 7:

Figure 7: PLL multiplier values and MODE pins

	Oscillator	MC	DDE	Tile	PLL Ratio	PLL	setting	gs	
	Frequency	1	0	Frequency		OD	F	R	
e 7:	3.25-10 MHz	0	0	130-400 MHz	40	1	159	0	
lier	9-25 MHz	1	1	144-400 MHz	16	1	63	0	
and	25-50 MHz	1	0	167-400 MHz	8	1	31	0	
oins	50-100 MHz	0	1	196-400 MHz	4	1	15	0	

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Figure 7 also lists the values of OD, F and R, which are the registers that define the ratio of the tile frequency to the oscillator frequency:

$$F_{core} = F_{osc} \times \frac{F+1}{2} \times \frac{1}{R+1} \times \frac{1}{OD+1}$$

OD, *F* and *R* must be chosen so that $0 \le R \le 63$, $0 \le F \le 4095$, $0 \le OD \le 7$, and $260MHz \le F_{osc} \times \frac{F+1}{2} \times \frac{1}{R+1} \le 1.3GHz$. The *OD*, *F*, and *R* values can be modified by writing to the digital node PLL configuration register.

The MODE pins must be held at a static value during and after deassertion of the system reset.

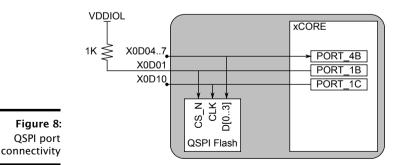
If a different tile frequency is required (eq, 500 MHz), then the PLL must be reprogrammed after boot to provide the required tile frequency. The XMOS tools perform this operation by default. Further details on configuring the clock can be found in the xCORE-200 Clock Frequency Control document.

8 Boot Procedure

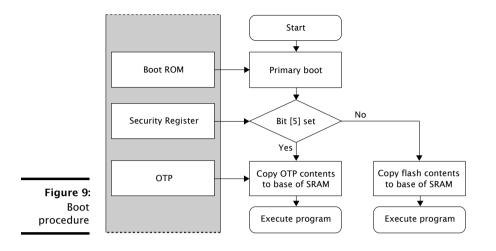
The device is kept in reset by driving RST_N low. When in reset, all GPIO pins have a pull-down enabled. The processor must be held in reset until VDDIOL is in spec for at least 1 ms. When the device is taken out of reset by releasing RST_N the processor starts its internal reset process. After 15-150 μ s (depending on the input clock) the processor boots.

Pin X2D06 must be pulled high with an external pull-up whilst the chip comes out of reset, to ensure that tile 2 will boot from link. X2D04, X2D05, and X2D07 should be kept low whilst the chip comes out of reset.

The device boots from a QSPI flash (IS25LQ016B) that is embedded in the device. The QSPI flash is connected to the ports on Tile 0 as shown in Figure 8. An external 1K resistor must connect X0D01 to VDDIOL, X0D10 should ideally not be connected. If X0D10 is connected, then a 150 ohm series resistor close to the device is recommended. X0D04..X0D07 should be not connected.



The xCORE Tile boot procedure is illustrated in Figure 9. If bit 5 of the security register (see $\{9,1\}$) is set, the device boots from OTP. Otherwise, the device boots from the internal flash.



The boot image has the following format:

- A 32-bit program size *s* in words.
- Program consisting of $s \times 4$ bytes.
- A 32-bit CRC, or the value 0x0D15AB1E to indicate that no CRC check should be performed.

The program size and CRC are stored least significant byte first. The program is loaded into the lowest memory address of RAM, and the program is started from that address. The CRC is calculated over the byte stream represented by the program size and the program itself. The polynomial used is 0xEDB88320 (IEEE 802.3); the CRC register is initialized with 0xFFFFFFFF and the residue is inverted to produce the CRC.

8.1 Security register

The security register enables security features on the xCORE tile. The features shown in Figure 10 provide a strong level of protection and are sufficient for providing strong IP security.

9 Memory

9.1 OTP

Each xCORE Tile integrates 8 KB one-time programmable (OTP) memory along with a security register that configures system wide security features. The OTP holds data in four sectors each containing 512 rows of 32 bits which can be used to implement secure bootloaders and store encryption keys. Data for the security

Feature	Bit	Description
Disable JTAG	0	The JTAG interface is disabled, making it impossible for the tile state or memory content to be accessed via the JTAG interface.
Disable Link access	1	Other tiles are forbidden access to the processor state via the system switch. Disabling both JTAG and Link access transforms an xCORE Tile into a "secure island" with other tiles free for non-secure user application code.
Secure Boot	5	The xCORE Tile is forced to boot from address 0 of the OTP, allowing the xCORE Tile boot ROM to be bypassed (see §8).
Redundant rows	7	Enables redundant rows in OTP.
Sector Lock 0	8	Disable programming of OTP sector 0.
Sector Lock 1	9	Disable programming of OTP sector 1.
Sector Lock 2	10	Disable programming of OTP sector 2.
Sector Lock 3	11	Disable programming of OTP sector 3.
OTP Master Lock	12	Disable OTP programming completely: disables up dates to all sectors and security register.
Disable JTAG-OTP	13	Disable all (read & write) access from the JTAG inter face to this OTP.
Disable Global Debug	14	Disables access to the DEBUG_N pin.
	2115	General purpose software accessable security registe available to end-users.
	3122	General purpose user programmable JTAG UserIE code extension.

Figure 10: Security register features

register is loaded from the OTP on power up. All additional data in OTP is copied from the OTP to SRAM and executed first on the processor.

The OTP memory is programmed using three special I/O ports: the OTP address port is a 16-bit port with resource ID 0x100200, the OTP data is written via a 32-bit port with resource ID 0x200100, and the OTP control is on a 16-bit port with ID 0x100300. Programming is performed through libotp and xburn.

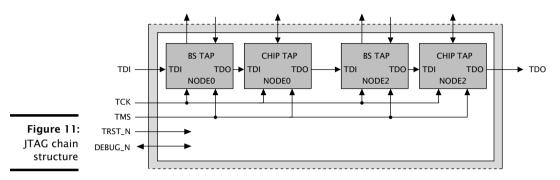
9.2 SRAM

Each xCORE Tile integrates a single 128KBSRAM bank for both instructions and data. All internal memory is 32 bits wide, and instructions are either 16-bit or 32-bit. Byte (8-bit), half-word (16-bit) or word (32-bit) accesses are supported and are executed within one tile clock cycle. There is no dedicated external memory interface, although data memory can be expanded through appropriate use of the ports.

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10 JTAG

The JTAG module can be used for loading programs, boundary scan testing, incircuit source-level debugging and programming the OTP memory.



The JTAG chain structure is illustrated in Figure 11. Directly after reset, two TAP controllers are present in the JTAG chain for each xCORE Tile: the boundary scan TAP and the chip TAP. The boundary scan TAP is a standard 1149.1 compliant TAP that can be used for boundary scan of the I/O pins. The chip TAP provides access into the xCORE Tile, switch and OTP for loading code and debugging.

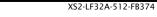
The TRST_N pin must be asserted low during and after power up for 100 ns. If JTAG is not required, the TRST_N pin can be tied to ground to hold the JTAG module in reset.

The DEBUG_N pin is used to synchronize the debugging of multiple xCORE Tiles. This pin can operate in both output and input mode. In output mode and when configured to do so, DEBUG_N is driven low by the device when the processor hits a debug break point. Prior to this point the pin will be tri-stated. In input mode and when configured to do so, driving this pin low will put the xCORE Tile into debug mode. Software can set the behavior of the xCORE Tile based on this pin. This pin should have an external pull up of $4K7-47K\Omega$ or left not connected in single core applications.

The JTAG device identification register can be read by using the IDCODE instruction. Its contents are specified in Figure 12.

	Bit	31											De	evice	Ide	ntifi	catio	n Re	egist	er											E	Bit0
Figure 12:		Ver	sion								Pa	rt N	umb	er										Man	ufact	ture	r Ide	ntit	y			1
IDCODE	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	0	0	1	1	0	0	0	1	1	0	0	1	1
return value		(0			(D			()			()			e	5			6	5				3			1	3	_

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The JTAG usercode register can be read by using the USERCODE instruction. Its contents are specified in Figure 13. The OTP User ID field is read from bits [22:31] of the security register on xCORE Tile 0, *see* §9.1 (all zero on unprogrammed devices).

Figure 13: USERCODE return value

	Bit	31												ι	Jser	code	Reg	giste	r												В	it0
				0	TP U	lser	ID					Unu	ised									Silic	on I	Revis	ion							
-	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
5		()			()			. ())			Z	2			5	3			0)			()			0)	

11 Board Integration

The device has the following power supply pins:

- ▶ VDD pins for the xCORE Tile
- ▶ VDDIO pins for the I/O lines
- PLL_AVDD pins for the PLL
- OTP_VCC pins for the OTP

Several pins of each type are provided to minimize the effect of inductance within the package, all of which must be connected. The power supplies must be brought up monotonically and input voltages must not exceed specification at any time.

The VDD supply must ramp from 0V to its final value within 10 ms to ensure correct startup.

The VDDIO and OTP_VCC supply must ramp to its final value before VDD reaches 0.4 V.

The PLL_AVDD supply should be separated from the other noisier supplies on the board. The PLL requires a very clean power supply, and a low pass filter (for example, a 2.2Ω resistor and 100 nF multi-layer ceramic capacitor) is recommended on this pin.

The following ground pins are provided:

- PLL_AGND for PLL_AVDD
- GND for all other supplies

All ground pins must be connected directly to the board ground.

The VDD and VDDIO supplies should be decoupled close to the chip by several 100 nF low inductance multi-layer ceramic capacitors between the supplies and GND (for example, 100nF 0402 for every other supply pin). The ground side of the decoupling capacitors should have as short a path back to the GND pins as possible. A bulk decoupling capacitor of at least 10 uF should be placed on each of these supplies.

RST_N is an active-low asynchronous-assertion global reset signal. Following a reset, the PLL re-establishes lock after which the device boots up according to the boot mode (*see* §8). RST_N and must be asserted low during and after power up for 100 ns.

11.1 Land patterns and solder stencils

The package is a 374 ball Fine Ball Grid Array (FBGA) on a 0.8 mm pitch.

The land patterns and solder stencils will depend on the PCB manufacturing process. We recommend you design them with using the IPC specifications *"Generic Requirements for Surface Mount Design and Land Pattern Standards"* IPC-7351B. This standard aims to achieve desired targets of heel, toe and side fillets for solder-joints. The mechanical drawings in Section 13 specify the dimensions and tolerances.

11.2 Ground and Thermal Vias

Vias next to each ground ball into the ground plane of the PCB are recommended for a low inductance ground connection and good thermal performance.

11.3 Moisture Sensitivity

XMOS devices are, like all semiconductor devices, susceptible to moisture absorption. When removed from the sealed packaging, the devices slowly absorb moisture from the surrounding environment. If the level of moisture present in the device is too high during reflow, damage can occur due to the increased internal vapour pressure of moisture. Example damage can include bond wire damage, die lifting, internal or external package cracks and/or delamination.

All XMOS devices are Moisture Sensitivity Level (MSL) 3 - devices have a shelf life of 168 hours between removal from the packaging and reflow, provided they are stored below 30C and 60% RH. If devices have exceeded these values or an included moisture indicator card shows excessive levels of moisture, then the parts should be baked as appropriate before use. This is based on information from *Joint IPC/JEDEC Standard For Moisture/Reflow Sensitivity Classification For Nonhermetic Solid State Surface-Mount Devices* J-STD-020 Revision D.

12 DC and Switching Characteristics

6	B		T)/D	BAAN	UNUTC	NI
Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
VDD	Tile DC supply voltage	0.95	1.00	1.05	V	
VDDIO	I/O supply voltage	2.30	3.30	3.60	V	
VDDIOT_0	I/O supply voltage	2.25	3.30	3.60	V	
VDDIOT_1	I/O supply voltage	2.25	3.30	3.60	V	
USB_VDD	USB tile DC supply voltage	0.95	1.00	1.05	V	
VDD33	Peripheral supply	3.135	3.30	3.465	V	
PLL_AVDD	PLL analog supply	0.95	1.00	1.05	V	
CI	xCORE Tile I/O load capacitance			25	pF	
Та	Ambient operating temperature (Commercial)	0		70	°C	
	Ambient operating temperature (Industrial)	-40		85	°C	
Tj	Junction temperature			125	°C	
Tstg	Storage temperature	-65		150	°C	

12.1 Operating Conditions

Figure 14: Operating conditions

12.2 DC Characteristics, VDDIO=3V3

Symbol	Parameter	MIN	ТҮР	MAX	UNITS	Notes
V(IH)	Input high voltage	2.00		3.60	V	A
V(IL)	Input low voltage	-0.30		0.70	V	A
V(OH)	Output high voltage	2.20			V	B, C
V(OL)	Output low voltage			0.40	V	B, C
I(PU)	Internal pull-up current (Vin=0V)	-100			μA	D
I(PD)	Internal pull-down current (Vin=3.3V)			100	μA	D
I(LC)	Input leakage current	-10		10	μA	

Figure 15: DC characteristics

A All pins except power supply pins.

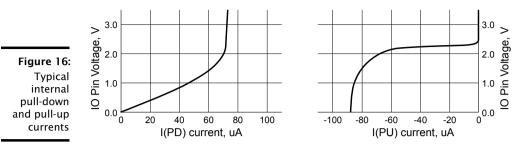
B Pins X1D40, X1D41, X1D42, X1D43, X1D26, X1D27, X3D40, X3D41, X3D42, X3D43, X3D26, and X3D27 are nominal 8 mA drivers, the remainder of the general-purpose I/Os are 4 mA.

C Measured with 4 mA drivers sourcing 4 mA, 8 mA drivers sourcing 8 mA.

D Used to guarantee logic state for an I/O when high impedance. The internal pull-ups/pull-downs should not be used to pull external circuitry. In order to pull the pin to the opposite state, a 4K7 resistor is recommended to overome the internal pull current.



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12.3 ESD Stress Voltage

Figure 17 ESD stress voltage

17:	Symbol	Parameter	MIN	ТҮР	MAX	UNITS	Notes
ess	HBM	Human body model	-2.00		2.00	KV	
age	CDM	Charged Device Model	-500		500	V	

12.4 Reset Timing

	Symbol	Parameters	MIN	ТҮР	MAX	UNITS	Notes
Figure 18:	T(RST)	Reset pulse width	5			μs	
Reset timing	T(INIT)	Initialization time			150	μs	А
	A Chouse the	time taken to start beating after DCT N b		امنعام			

A Shows the time taken to start booting after RST_N has gone high.

12.5 Power Consumption

	Symbol	Parameter	MIN	ТҮР	MAX	UNITS	Notes
	I(DDCQ)	Quiescent VDD current		45		mA	A, B, C
Figure 19:	PD	Tile power dissipation		325		µW/MIPS	A, D, E, F
xCORE Tile	IDD	Active VDD current		1140	1400	mA	A, G
currents	I(ADDPLL)	PLL_AVDD current		5	7	mA	Н

A Use for budgetary purposes only.

B Assumes typical tile and I/O voltages with no switching activity.

- C Includes PLL current.
- D Assumes typical tile and I/O voltages with nominal switching activity.
- E Assumes 1 MHz = 1 MIPS.
- F PD(TYP) value is the usage power consumption under typical operating conditions.
- G Measurement conditions: VDD = 1.0 V, VDDIO = 3.3 V, 25 °C, 500 MHz, average device resource usage.
- H PLL_AVDD = 1.0 V



The tile power consumption of the device is highly application dependent and should be used for budgetary purposes only.

More detailed power analysis can be found in the XS1-LF Power Consumption document.

12	2.6	Clock

Figure 20: Clock

Parameter	MIN	ТҮР	MAX	UNITS	Notes
Frequency	3.25	25	100	MHz	
Slew rate	0.10			V/ns	
Long term jitter (pk-pk)			2	%	А
Processor clock frequency			500	MHz	В
	Frequency Slew rate Long term jitter (pk-pk)	Frequency3.25Slew rate0.10Long term jitter (pk-pk)	Frequency3.2525Slew rate0.10Long term jitter (pk-pk)	Frequency3.2525100Slew rate0.10Long term jitter (pk-pk)2	Frequency3.2525100MHzSlew rate0.10V/nsLong term jitter (pk-pk)2%

A Percentage of CLK period.

B Assumes typical tile and I/O voltages with nominal activity.

Further details can be found in the XS1-LF Clock Frequency Control document,

12.7 xCORE Tile I/O AC Characteristics

	Symbol	Parameter	MIN	ТҮР	MAX	UNITS	Notes
	T(XOVALID)	Input data valid window	8			ns	
Figure 21:	T(XOINVALID)	Output data invalid window	9			ns	
I/O AC char- acteristics	T(XIFMAX)	Rate at which data can be sampled with respect to an external clock			60	MHz	

The input valid window parameter relates to the capability of the device to capture data input to the chip with respect to an external clock source. It is calculated as the sum of the input setup time and input hold time with respect to the external clock as measured at the pins. The output invalid window specifies the time for which an output is invalid with respect to the external clock. Note that these parameters are specified as a window rather than absolute numbers since the device provides functionality to delay the incoming clock with respect to the incoming data.

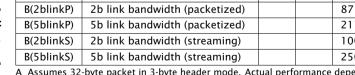
Information on interfacing to high-speed synchronous interfaces can be found in the XS1 Port I/O Timing document, X5821.

12.8 xConnect Link Performance

	Symbol	Parameter	MIN	ТҮР	MAX	UNITS	Notes
	B(2blinkP)	2b link bandwidth (packetized)			87	MBit/s	A, B
Figure 22:	B(5blinkP)	5b link bandwidth (packetized)			217	MBit/s	А, В
Link	B(2blinkS)	2b link bandwidth (streaming)			100	MBit/s	В
performance	B(5blinkS)	5b link bandwidth (streaming)			250	MBit/s	В

A Assumes 32-byte packet in 3-byte header mode. Actual performance depends on size of the header and payload.

B 7.5 ns symbol time.



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The asynchronous nature of links means that the relative phasing of CLK clocks is not important in a multi-clock system, providing each meets the required stability criteria.

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
f(TCK_D)	TCK frequency (debug)			18	MHz	
f(TCK_B)	TCK frequency (boundary scan)			10	MHz	
T(SETUP)	TDO to TCK setup time	5			ns	А
T(HOLD)	TDO to TCK hold time	5			ns	А
T(DELAY)	TCK to output delay			15	ns	В

12.9 JTAG Timing

Figure 23: JTAG timing

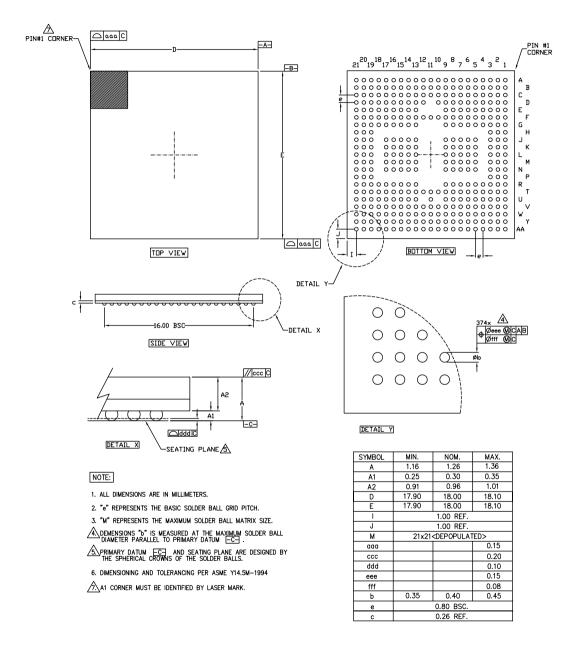
A Timing applies to TMS and TDI inputs.

B Timing applies to TDO output from negative edge of TCK.

All JTAG operations are synchronous to TCK apart from the global asynchronous reset TRST_N.



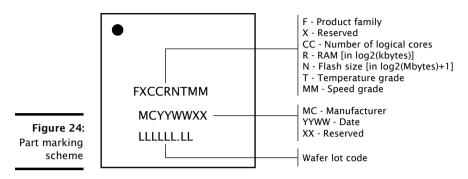
13 Package Information



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XS2-LF32A-512-FB374

13.1 Part Marking



14 Ordering Information

Figure 25:	Product Code	Marking	Qualification	Speed Grade
Orderable	XLF232-512-FB374-C40	L13292C40	Commercial	2000 MIPS
part numbers	XLF232-512-FB374-I40	L13292C40	Industrial	2000 MIPS

Appendices

A Configuration of the XLF232-512-FB374

The device is configured through banks of registers, as shown in Figure 26.

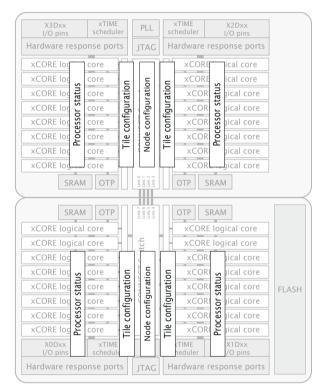


Figure 26: Registers

The following communication sequences specify how to access those registers. Any messages transmitted contain the most significant 24 bits of the channel-end to which a response is to be sent. This comprises the node-identifier and the channel number within the node. if no response is required on a write operation, supply 24-bits with the last 8-bits set, which suppresses the reply message. Any multi-byte data is sent most significant byte first.

A.1 Accessing a processor status register

The processor status registers are accessed directly from the processor instruction set. The instructions GETPS and SETPS read and write a word. The register number should be translated into a processor-status resource identifier by shifting the register number left 8 places, and ORing it with 0x0B. Alternatively, the functions getps(reg) and setps(reg,value) can be used from XC.



A.2 Accessing an xCORE Tile configuration register

xCORE Tile configuration registers can be accessed through the interconnect using the functions write_tile_config_reg(tileref, ...) and read_tile_config_reg(tile \rightarrow ref, ...), where tileref is the name of the xCORE Tile, e.g. tile[1]. These functions implement the protocols described below.

Instead of using the functions above, a channel-end can be allocated to communicate with the xCORE tile configuration registers. The destination of the channel-end should be set to 0xnnnnC20C where nnnnnn is the tile-identifier.

A write message comprises the following:

control-token	24-bit response	16-bit	32-bit	control-token
192	channel-end identifier	register number	data	1

The response to a write message comprises either control tokens 3 and 1 (for success), or control tokens 4 and 1 (for failure).

A read message comprises the following:

control-token	24-bit response	16-bit	control-token
193	channel-end identifier	register number	1

The response to the read message comprises either control token 3, 32-bit of data, and control-token 1 (for success), or control tokens 4 and 1 (for failure).

A.3 Accessing node configuration

Node configuration registers can be accessed through the interconnect using the functions write_node_config_reg(device, ...) and read_node_config_reg(device, \rightarrow ...), where device is the name of the node. These functions implement the protocols described below.

Instead of using the functions above, a channel-end can be allocated to communicate with the node configuration registers. The destination of the channel-end should be set to 0xnnnnc30c where nnnn is the node-identifier.

A write message comprises the following:

control-token	24-bit response	16-bit	32-bit	control-token
192	channel-end identifier	register number	data	1

The response to a write message comprises either control tokens 3 and 1 (for success), or control tokens 4 and 1 (for failure).

A read message comprises the following:

control-token	24-bit response	16-bit	control-token	
193	channel-end identifier	register number	1	

The response to a read message comprises either control token 3, 32-bit of data, and control-token 1 (for success), or control tokens 4 and 1 (for failure).

B Processor Status Configuration

The processor status control registers can be accessed directly by the processor using processor status reads and writes (use getps(reg) and setps(reg,value) for reads and writes).

Number	Perm	Description
0x00	RW	RAM base address
0x01	RW	Vector base address
0x02	RW	xCORE Tile control
0x03	RO	xCORE Tile boot status
0x05	RW	Security configuration
0x06	RW	Ring Oscillator Control
0x07	RO	Ring Oscillator Value
0x08	RO	Ring Oscillator Value
0x09	RO	Ring Oscillator Value
0x0A	RO	Ring Oscillator Value
0x0C	RO	RAM size
0x10	DRW	Debug SSR
0x11	DRW	Debug SPC
0x12	DRW	Debug SSP
0x13	DRW	DGETREG operand 1
0x14	DRW	DGETREG operand 2
0x15	DRW	Debug interrupt type
0x16	DRW	Debug interrupt data
0x18	DRW	Debug core control
0x20 0x27	DRW	Debug scratch
0x30 0x33	DRW	Instruction breakpoint address
0x40 0x43	DRW	Instruction breakpoint control
0x50 0x53	DRW	Data watchpoint address 1
0x60 0x63	DRW	Data watchpoint address 2
0x70 0x73	DRW	Data breakpoint control register
0x80 0x83	DRW	Resources breakpoint mask
0x90 0x93	DRW	Resources breakpoint value
0x9C 0x9F	DRW	Resources breakpoint control register

Figure 27:

Summary

X008766,

B.1 RAM base address: 0x00

This register contains the base address of the RAM. It is initialized to 0x00040000.

0x00: RAM base address

00:	Bits	Perm	Init	Description
ase	31:2	RW		Most significant 16 bits of all addresses.
ess	1:0	RO	-	Reserved

B.2 Vector base address: 0x01

Base address of event vectors in each resource. On an interrupt or event, the 16 most significant bits of the destination address are provided by this register; the least significant 16 bits come from the event vector.

0x01: Vector base address

	Bits	Perm	Init	Description
•	31:18	RW		The event and interrupt vectors.
	17:0	RO	-	Reserved

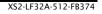
B.3 xCORE Tile control: 0x02

Register to control features in the xCORE tile

Bits	Perm	Init	Description
31:26	RO	-	Reserved
25:18	RW	0	RGMII TX data delay value (in PLL output cycle increments)
17:9	RW	0	RGMII TX clock divider value. TX clk rises when counter (clocked by PLL output) reaches this value and falls when counter reaches (value»1). Value programmed into this field should be actual divide value required minus 1
8	RW	0	Enable RGMII interface periph ports
7:6	RO	-	Reserved
5	RW	0	Select the dynamic mode (1) for the clock divider when the clock divider is enabled. In dynamic mode the clock divider is only activated when all active threads are paused. In static mode the clock divider is always enabled.
4	RW	0	Enable the clock divider. This divides the output of the PLL to facilitate one of the low power modes.
3:0	RO	-	Reserved

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0x02: xCORE Tile control



B.4 xCORE Tile boot status: 0x03

This read-only register describes the boot status of the xCORE tile.

Bits	Perm	Init	Description
31:24	RO	-	Reserved
23:16	RO		Processor number.
15:9	RO	-	Reserved
8	RO		Overwrite BOOT_MODE.
7:6	RO	-	Reserved
5	RO		Indicates if core1 has been powered off
4	RO		Cause the ROM to not poll the OTP for correct read levels
3	RO		Boot ROM boots from RAM
2	RO		Boot ROM boots from JTAG
1:0	RO		The boot PLL mode pin value.

0x03: xCORE Tile boot status

B.5 Security configuration: 0x05

Copy of the security register as read from OTP.

Bits	Perm	Init	Description
31	RW		Disables write permission on this register
30:15	RO	-	Reserved
14	RW		Disable access to XCore's global debug
13	RO	-	Reserved
12	RW		lock all OTP sectors
11:8	RW		lock bit for each OTP sector
7	RW		Enable OTP reduanacy
6	RO	-	Reserved
5	RW		Override boot mode and read boot image from OTP
4	RW		Disable JTAG access to the PLL/BOOT configuration registers
3:1	RO	-	Reserved
0	RW		Disable access to XCore's JTAG debug TAP

0x05: Security configuration

B.6 Ring Oscillator Control: 0x06

There are four free-running oscillators that clock four counters. The oscillators can be started and stopped using this register. The counters should only be read when the ring oscillator has been stopped for at least 10 core clock cycles (this can be achieved by inserting two nop instructions between the SETPS and GETPS). The counter values can be read using four subsequent registers. The ring oscillators are asynchronous to the xCORE tile clock and can be used as a source of random bits.

0x06: Ring Oscillator Control

_	Bits	Perm	Init	Description
6:	31:2	RO	-	Reserved
g or	1	RW	0	Core ring oscillator enable.
ol	0	RW	0	Peripheral ring oscillator enable.

B.7 Ring Oscillator Value: 0x07

This register contains the current count of the xCORE Tile Cell ring oscillator. This value is not reset on a system reset.

0x07 Ring Oscillator Value

: 07: ing	Bits	Perm	Init	Description
tor	31:16	RO	-	Reserved
lue	15:0	RO	0	Ring oscillator Counter data.

B.8 Ring Oscillator Value: 0x08

This register contains the current count of the xCORE Tile Wire ring oscillator. This value is not reset on a system reset.

0x08: Ring Oscillator Value

8: a	Bits	Perm	Init	Description
g or	31:16	RO	-	Reserved
e	15:0	RO	0	Ring oscillator Counter data.

B.9 Ring Oscillator Value: 0x09

This register contains the current count of the Peripheral Cell ring oscillator. This value is not reset on a system reset.

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0x09: Ring	Bits	Perm	Init	Description
Oscillator	31:16	RO	-	Reserved
Value	15:0	RO	0	Ring oscillator Counter data.

B.10 Ring Oscillator Value: 0x0A

This register contains the current count of the Peripheral Wire ring oscillator. This value is not reset on a system reset.

0x0A Rin<u>c</u> Oscillato Value

(0A: Ring	Bits	Perm	Init	Description
ator	31:16	RO	-	Reserved
alue	15:0	RO	0	Ring oscillator Counter data.

B.11 RAM size: 0x0C

The size of the RAM in bytes

0x0C: RAM size

	Bits	Perm	Init	Description
:	31:2	RO		Most significant 16 bits of all addresses.
e	1:0	RO	-	Reserved

B.12 Debug SSR: 0x10

This register contains the value of the SSR register when the debugger was called.

Bits	Perm	Init	Description
31:11	RO	-	Reserved
10	DRW		Address space indentifier
9	DRW		Determines the issue mode (DI bit) upon Kernel Entry after Exception or Interrupt.
8	RO		Determines the issue mode (DI bit).
7	DRW		When 1 the thread is in fast mode and will continually issue.
6	DRW		When 1 the thread is paused waiting for events, a lock or another resource.
5	RO	-	Reserved
4	DRW		1 when in kernel mode.
3	DRW		1 when in an interrupt handler.
2	DRW		1 when in an event enabling sequence.
1	DRW		When 1 interrupts are enabled for the thread.
0	DRW		When 1 events are enabled for the thread.

0x10: Debug SSR

B.13 Debug SPC: 0x11

This register contains the value of the SPC register when the debugger was called.

0x11:	Bits	Perm	Init	Description
Debug SPC	31:0	DRW		Value.

B.14 Debug SSP: 0x12

This register contains the value of the SSP register when the debugger was called.

0x12:	Bits	Perm	Init	Description
Debug SSP	31:0	DRW		Value.

B.15 DGETREG operand 1: 0x13

The resource ID of the logical core whose state is to be read.

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0x13:	Bits	Perm	Init	Description
DGETREG	31:8	RO	-	Reserved
operand 1	7:0	DRW		Thread number to be read

B.16 DGETREG operand 2: 0x14

Register number to be read by DGETREG

0x14 DGETREG operand 2

4:	Bits	Perm	Init	Description
G.	31:5	RO	-	Reserved
2	4:0	DRW		Register number to be read

B.17 Debug interrupt type: 0x15

Register that specifies what activated the debug interrupt.

Bits	Perm	Init	Description
31:18	RO	-	Reserved
17:16	DRW		Number of the hardware breakpoint/watchpoint which caused the interrupt (always 0 for =HOST= and =DCALL=). If multiple breakpoints/watchpoints trigger at once, the lowest number is taken.
15:8	DRW		Number of thread which caused the debug interrupt (always 0 in the case of =HOST=).
7:3	RO	-	Reserved
2:0	DRW	0	Indicates the cause of the debug interrupt 1: Host initiated a debug interrupt through JTAG 2: Program executed a DCALL instruction 3: Instruction breakpoint 4: Data watch point 5: Resource watch point

0x15: Debug interrupt type

B.18 Debug interrupt data: 0x16

On a data watchpoint, this register contains the effective address of the memory operation that triggered the debugger. On a resource watchpoint, it countains the resource identifier.

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0x16:				
Debug	Bits	Perm	Init	Description
interrupt data	31:0	DRW		Value.

B.19 Debug core control: 0x18

This register enables the debugger to temporarily disable logical cores. When returning from the debug interrupts, the cores set in this register will not execute. This enables single stepping to be implemented.

0x18: Debug core control

Bits	Perm	Init	Description
31:8	RO	-	Reserved
7:0	DRW		1-hot vector defining which threads are stopped when not in debug mode. Every bit which is set prevents the respective thread from running.

B.20 Debug scratch: 0x20 .. 0x27

A set of registers used by the debug ROM to communicate with an external debugger, for example over JTAG. This is the same set of registers as the Debug Scratch registers in the xCORE tile configuration.

0x20 .. 0x27: Debug scratch

x27: bug	Bits	Perm	Init	Description
atch	31:0	DRW		Value.

B.21 Instruction breakpoint address: 0x30 .. 0x33

This register contains the address of the instruction breakpoint. If the PC matches this address, then a debug interrupt will be taken. There are four instruction breakpoints that are controlled individually.

0x30 .. 0x33: Instruction breakpoint address

ction point	Bits	Perm	Init	Description
dress	31:0	DRW		Value.

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B.22 Instruction breakpoint control: 0x40 .. 0x43

This register controls which logical cores may take an instruction breakpoint, and under which condition.

Bits	Perm	Init	Description	
31:24	RO	-	Reserved	
23:16	DRW	0	A bit for each thread in the machine allowing the breakpoint to be enabled individually for each thread.	
15:2	RO	-	Reserved	
1	DRW	0	When 0 break when PC == IBREAK_ADDR. When 1 = break when PC != IBREAK_ADDR.	
0	DRW	0	When 1 the instruction breakpoint is enabled.	

0x40 .. 0x43: Instruction breakpoint control

B.23 Data watchpoint address 1: 0x50 .. 0x53

This set of registers contains the first address for the four data watchpoints.

0x50 .. 0x53: Data watchpoint address 1

Data 1point	Bits	Perm	Init	Description
ress 1	31:0	DRW		Value.

B.24 Data watchpoint address 2: 0x60 .. 0x63

This set of registers contains the second address for the four data watchpoints.

0x60 .. 0x63: Data watchpoint address 2

Data Chpoint	Bits	Perm	Init	Description
dress 2	31:0	DRW		Value.

B.25 Data breakpoint control register: 0x70 .. 0x73

This set of registers controls each of the four data watchpoints.

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XS2-LF32A-512-FB374

	Bits	Perm	Init	Description
	31:24	RO	-	Reserved
	23:16	DRW	0	A bit for each thread in the machine allowing the breakpoint to be enabled individually for each thread.
0x70 0x73:	15:3	RO	-	Reserved
Data breakpoint control	2	DRW	0	When 1 the breakpoints will be be triggered on loads.
	1	DRW	0	Determines the break condition: $0 = A AND B$, $1 = A OR B$.
register	0	DRW	0	When 1 the instruction breakpoint is enabled.

B.26 Resources breakpoint mask: 0x80 .. 0x83

This set of registers contains the mask for the four resource watchpoints.

0x80 0x83: Resources				
breakpoint	Bits	Perm	Init	Description
mask	31:0	DRW		Value.

B.27 Resources breakpoint value: 0x90 .. 0x93

This set of registers contains the value for the four resource watchpoints.

0x90 0x93: Resources				
breakpoint	Bits	Perm	Init	Description
value	31:0	DRW		Value.

B.28 Resources breakpoint control register: 0x9C .. 0x9F

This set of registers controls each of the four resource watchpoints.

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	Bits	Perm	Init	Description
	31:24	RO	-	Reserved
0x9C 0x9F: Resources breakpoint control	23:16	DRW	0	A bit for each thread in the machine allowing the breakpoint to be enabled individually for each thread.
	15:2	RO	-	Reserved
	1	DRW	0	When 0 break when condition A is met. When 1 = break when condition B is met.
register	0	DRW	0	When 1 the instruction breakpoint is enabled.



C Tile Configuration

The xCORE Tile control registers can be accessed using configuration reads and writes (use write_tile_config_reg(tileref, ...) and read_tile_config_reg(tileref, \rightarrow ...) for reads and writes).

Number	Perm	Description	
0x00	CRO	Device identification	
0x01	CRO	xCORE Tile description 1	
0x02	CRO	xCORE Tile description 2	
0x04	CRW	Control PSwitch permissions to debug registers	
0x05	CRW	Cause debug interrupts	
0x06	CRW	xCORE Tile clock divider	
0x07	CRO	Security configuration	
0x20 0x27	CRW	Debug scratch	
0x40	CRO	PC of logical core 0	
0x41	CRO	PC of logical core 1	
0x42	CRO	PC of logical core 2	
0x43	CRO	PC of logical core 3	
0x44	CRO	PC of logical core 4	
0x45	CRO	PC of logical core 5	
0x46	CRO	PC of logical core 6	
0x47	CRO	PC of logical core 7	
0x60	CRO	SR of logical core 0	
0x61	CRO	SR of logical core 1	
0x62	CRO	SR of logical core 2	
0x63	CRO	SR of logical core 3	
0x64	CRO	SR of logical core 4	
0x65	CRO	SR of logical core 5	
0x66	CRO	SR of logical core 6	
0x67	CRO	SR of logical core 7	

Figure 28: Summary

C.1 Device identification: 0x00

This register identifies the xCORE Tile

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	Bits	Perm	Init	Description
	31:24	CRO		Processor ID of this XCore.
0x00: Device identification	23:16	CRO		Number of the node in which this XCore is located.
	15:8	CRO		XCore revision.
	7:0	CRO		XCore version.

C.2 xCORE Tile description 1: 0x01

This register describes the number of logical cores, synchronisers, locks and channel ends available on this xCORE tile.

Bits	Perm	Init	Description
31:24	CRO		Number of channel ends.
23:16	CRO		Number of the locks.
15:8	CRO		Number of synchronisers.
7:0	RO	-	Reserved

C.3 xCORE Tile description 2: 0x02

This register describes the number of timers and clock blocks available on this xCORE tile.

0x02: xCORE Tile description 2

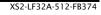
0x01: xCORE Tile description 1

	Bits	Perm	Init	Description
x02:	31:16	RO	-	Reserved
Tile	15:8	CRO		Number of clock blocks.
on 2	7:0	CRO		Number of timers.

C.4 Control PSwitch permissions to debug registers: 0x04

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This register can be used to control whether the debug registers (marked with permission CRW) are accessible through the tile configuration registers. When this bit is set, write -access to those registers is disabled, preventing debugging of the xCORE tile over the interconnect.



0x04: Control PSwitch permissions to debug registers

Bits	Perm	Init	Description
31	CRW	0	When 1 the PSwitch is restricted to RO access to all CRW registers from SSwitch, XCore(PS_DBG_Scratch) and JTAG
30:1	RO	-	Reserved
0	CRW	0	When 1 the PSwitch is restricted to RO access to all CRW registers from SSwitch

C.5 Cause debug interrupts: 0x05

This register can be used to raise a debug interrupt in this xCORE tile.

0x05: Cause debug interrupts

Bits	Perm	Init	Description
31:2	RO	-	Reserved
1	CRW	0	1 when the processor is in debug mode.
0	CRW	0	Request a debug interrupt on the processor.

C.6 xCORE Tile clock divider: 0x06

This register contains the value used to divide the PLL clock to create the xCORE tile clock. The divider is enabled under control of the tile control register

0x06: xCORE Tile clock divider

Bits	Perm	Init	Description
31	CRW	0	Clock disable. Writing '1' will remove the clock to the tile.
30:16	RO	-	Reserved
15:0	CRW	0	Clock divider.

C.7 Security configuration: 0x07

Copy of the security register as read from OTP.

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	Bits	Perm	Init	Description
	31	CRO		Disables write permission on this register
	30:15	RO	-	Reserved
	14	CRO		Disable access to XCore's global debug
	13	RO	-	Reserved
	12	CRO		lock all OTP sectors
	11:8	CRO		lock bit for each OTP sector
	7	CRO		Enable OTP reduanacy
	6	RO	-	Reserved
	5	CRO		Override boot mode and read boot image from OTP
	4	CRO		Disable JTAG access to the PLL/BOOT configuration registers
,	3:1	RO	-	Reserved
1	0	CRO		Disable access to XCore's JTAG debug TAP

0x07 Security configuration

C.8 Debug scratch: 0x20 .. 0x27

A set of registers used by the debug ROM to communicate with an external debugger, for example over the switch. This is the same set of registers as the Debug Scratch registers in the processor status.

0x20 .. 0x27: Debug scratch

0x27: Debug	Bits	Perm	Init	Description
ratch	31:0	CRW		Value.

C.9 PC of logical core 0: 0x40

Value of the PC of logical core 0.

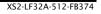
0x40 PC of logical core 0

9 x40: gical	Bits	Perm	Init	Description
ore 0	31:0	CRO		Value.

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C.10 PC of logical core 1: 0x41

Value of the PC of logical core 1.



0x41: PC of logical core 1

Bits	Perm	Init	Description
31:0	CRO		Value.

C.11 PC of logical core 2: 0x42

Value of the PC of logical core 2.

0x42: PC of logical core 2

Bits	Perm	Init	Description
31:0	CRO		Value.

C.12 PC of logical core 3: 0x43

Value of the PC of logical core 3.

0x43:				
PC of logical	Bits	Perm	Init	Description
core 3	31:0	CRO		Value.

C.13 PC of logical core 4: 0x44

Value of the PC of logical core 4.

0x44 PC of logical core 4

0x44: ogical	Bits	Perm	Init	Description
core 4	31:0	CRO		Value.

C.14 PC of logical core 5: 0x45

Value of the PC of logical core 5.

0x45: PC of logical core 5

). 	Bits	Perm	Init	Description
5	31:0	CRO		Value.

Bits

31:0

C.15 PC of logical core 6: 0x46

Value of the PC of logical core 6.

0x46: PC of logical core 6

 Perm
 Init
 Description

 CRO
 Value.

C.16 PC of logical core 7: 0x47

Value of the PC of logical core 7.

0x47 PC of logical core 7

0x47: gical	Bits	Perm	Init	Description
ore 7	31:0	CRO		Value.

C.17 SR of logical core 0: 0x60

Value of the SR of logical core 0

0x60: SR of logical core 0

0x60: ogical	Bits	Perm	Init	Description
ore 0	31:0	CRO		Value.

C.18 SR of logical core 1: 0x61

Value of the SR of logical core 1

0x61 SR of logical core 1

61: ical	Bits	Perm	Init	Description
e 1	31:0	CRO		Value.

C.19 SR of logical core 2: 0x62

Value of the SR of logical core 2



0x62: SR of logical core 2

Bits	Perm	Init	Description
31:0	CRO		Value.

C.20 SR of logical core 3: 0x63

Value of the SR of logical core 3

0x63: SR of logical core 3

Bits	Perm	Init	Description
31:0	CRO		Value.

C.21 SR of logical core 4: 0x64

Value of the SR of logical core 4

Ox64:
SR of logical
core 4BitsPermInitDescription31:0CROValue.

C.22 SR of logical core 5: 0x65

Value of the SR of logical core 5

0x65 SR of logical core 5

0x65: ogical	Bits	Perm	Init	Description
ore 5	31:0	CRO		Value.

C.23 SR of logical core 6: 0x66

Value of the SR of logical core 6

0x66: SR of logical core 6

Bits	Perm	Init	Description
31:0	CRO		Value.

C.24 SR of logical core 7: 0x67

Value of the SR of logical core 7

0x67:				
SR of logical	Bits	Perm	Init	Description
core 7	31:0	CRO		Value.



D Node Configuration

The digital node control registers can be accessed using configuration reads and writes (use write_node_config_reg(device, ...) and read_node_config_reg(device, \rightarrow ...) for reads and writes).

Number	Perm	Description	
0x00	RO	Device identification	
0x01	RO	System switch description	
0x04	RW	Switch configuration	
0x05	RW	Switch node identifier	
0x06	RW	PLL settings	
0x07	RW	System switch clock divider	
0x08	RW	Reference clock	
0x09	R	System JTAG device ID register	
0x0A	R	System USERCODE register	
0x0C	RW	Directions 0-7	
0x0D	RW	Directions 8-15	
0x10	RW	DEBUG_N configuration, tile 0	
0x11	RW	DEBUG_N configuration, tile 1	
0x1F	RO	Debug source	
0x20 0x28	RW	Link status, direction, and network	
0x40 0x47	RO	PLink status and network	
0x80 0x88	RW	Link configuration and initialization	
0xA0 0xA7	RW	Static link configuration	

Figure 29: Summary

D.1 Device identification: 0x00

This register contains version and revision identifiers and the mode-pins as sampled at boot-time.

	Bits	Perm	Init	Description
	31:24	RO	-	Reserved
0x00:	23:16	RO		Sampled values of BootCtl pins on Power On Reset.
Device	15:8	RO		SSwitch revision.
tification	7:0	RO		SSwitch version.

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identi

D.2 System switch description: 0x01

This register specifies the number of processors and links that are connected to this switch.

0x01: System switch description

	Bits	Perm	Init	Description
-	31:24	RO	-	Reserved
l: n	23:16	RO		Number of SLinks on the SSwitch.
h	15:8	RO		Number of processors on the SSwitch.
n	7:0	RO		Number of processors on the device.

D.3 Switch configuration: 0x04

This register enables the setting of two security modes (that disable updates to the PLL or any other registers) and the header-mode.

Bits	Perm	Init	Description
31	RW	0	0 = SSCTL registers have write access. $1 = SSCTL$ registers can not be written to.
30:9	RO	-	Reserved
8	RW	0	0 = PLL_CTL_REG has write access. 1 = PLL_CTL_REG can not be written to.
7:1	RO	-	Reserved
0	RW	0	0 = 2-byte headers, 1 = 1-byte headers (reset as 0).

0x04: Switch configuration

D.4 Switch node identifier: 0x05

This register contains the node identifier.

0x05
Switch node
identifier

0x05:	Bits	Perm	Init	Description
node	31:16	RO	-	Reserved
ntifier	15:0	RW	0	The unique ID of this node.

D.5 PLL settings: 0x06

An on-chip PLL multiplies the input clock up to a higher frequency clock, used to clock the I/O, processor, and switch, see Oscillator. Note: a write to this register will cause the tile to be reset.

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Bits	Perm	Init	Description
31	RW		If set to 1, the chip will not be reset
30	RW		If set to 1, the chip will not wait for the PLL to re-lock. Only use this if a gradual change is made to the PLL
29	DW		If set to 1, set the PLL to be bypassed
28	DW		If set to 1, set the boot mode to boot from JTAG
27:26	RO	-	Reserved
25:23	RW		Output divider value range from 1 (8'h0) to 250 (8'hF9). P value.
22:21	RO	-	Reserved
20:8	RW		Feedback multiplication ratio, range from 1 (8'h0) to 255 (8'hFE). M value.
7	RO	-	Reserved
6:0	RW		Oscilator input divider value range from 1 (8'h0) to 32 (8'h0F). N value.

0x06: PLL settings

D.6 System switch clock divider: 0x07

Sets the ratio of the PLL clock and the switch clock.

0x07: System switch clock divider

Bits	Perm	Init	Description
31:16	RO	-	Reserved
15:0	RW	0	SSwitch clock generation

D.7 Reference clock: 0x08

Sets the ratio of the PLL clock and the reference clock used by the node.

0x08:	Bits	Perm	Init	Description
Reference clock	31:16	RO	-	Reserved
	15:0	RW	3	Software ref. clock divider

D.8 System JTAG device ID register: 0x09

0x09: System JTAG device ID register

	Bits	Perm	Init	Description
-	31:28	RO		
9: G	27:12	RO		
D	11:1	RO		
er	0	RO		

D.9 System USERCODE register: 0x0A

0x0A System USERCODE register

4: n	Bits	Perm	Init	Description
E	31:18	RO		JTAG USERCODE value programmed into OTP SR
er	17:0	RO		metal fixable ID code

D.10 Directions 0-7: 0x0C

This register contains eight directions, for packets with a mismatch in bits 7..0 of the node-identifier. The direction in which a packet will be routed is goverened by the most significant mismatching bit.

Bits	Perm	Init	Description
31:28	RW	0	The direction for packets whose dimension is 7.
27:24	RW	0	The direction for packets whose dimension is 6.
23:20	RW	0	The direction for packets whose dimension is 5.
19:16	RW	0	The direction for packets whose dimension is 4.
15:12	RW	0	The direction for packets whose dimension is 3.
11:8	RW	0	The direction for packets whose dimension is 2.
7:4	RW	0	The direction for packets whose dimension is 1.
3:0	RW	0	The direction for packets whose dimension is 0.

0x0C: Directions 0-7

D.11 Directions 8-15: 0x0D

This register contains eight directions, for packets with a mismatch in bits 15..8 of the node-identifier. The direction in which a packet will be routed is goverened by the most significant mismatching bit.

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	Bits	Perm	Init	Description
	31:28	RW	0	The direction for packets whose dimension is F.
	27:24	RW	0	The direction for packets whose dimension is E.
	23:20	RW	0	The direction for packets whose dimension is D.
	19:16	RW	0	The direction for packets whose dimension is C.
	15:12	RW	0	The direction for packets whose dimension is B.
0x0D: ections	11:8	RW	0	The direction for packets whose dimension is A.
	7:4	RW	0	The direction for packets whose dimension is 9.
8-15	3:0	RW	0	The direction for packets whose dimension is 8.

D.12 DEBUG_N configuration, tile 0: 0x10

Configures the behavior of the DEBUG_N pin.

0x1 DEBUG_N con figuratio tile

Directions 8-15

	Bits	Perm	Init	Description
10: on-	31:2	RO	-	Reserved
on,	1	RW	0	Set 1 to enable GlobalDebug to generate debug request to XCore.
e 0	0	RW	0	Set 1 to enable inDebug bit to drive GlobalDebug.

D.13 DEBUG_N configuration, tile 1: 0x11

Configures the behavior of the DEBUG_N pin.

0x1 DEBUG_N co figuratio tile

	Bits	Perm	Init	Description
1: 0n-	31:2	RO	-	Reserved
on,	1	RW	0	Set 1 to enable GlobalDebug to generate debug request to XCore.
21	0	RW	0	Set 1 to enable inDebug bit to drive GlobalDebug.

D.14 Debug source: 0x1F

Contains the source of the most recent debug event.

 $\cdot X MOS$

Bits	Perm	Init	Description
31:5	RO	-	Reserved
4	RW		If set, external pin, is the source of last GlobalDebug event.
3:2	RO	-	Reserved
1	RW		If set, XCore1 is the source of last GlobalDebug event.
0	RW		If set, XCore0 is the source of last GlobalDebug event.

0x1F: Debug source

D.15 Link status, direction, and network: 0x20 .. 0x28

These registers contain status information for low level debugging (read-only), the network number that each link belongs to, and the direction that each link is part of. The registers control links 0..7.

Bits	Perm	Init	Description
31:26	RO	-	Reserved
25:24	RO		Identify the SRC_TARGET type 0 - SLink, 1 - PLink, 2 - SSCTL, 3 - Undefine.
23:16	RO		When the link is in use, this is the destination link number to which all packets are sent.
15:12	RO	-	Reserved
11:8	RW	0	The direction that this link operates in.
7:6	RO	-	Reserved
5:4	RW	0	Determines the network to which this link belongs, reset as 0.
3	RO	-	Reserved
2	RO		1 when the current packet is considered junk and will be thrown away.
1	RO		1 when the dest side of the link is in use.
0	RO		1 when the source side of the link is in use.

0x20 .. 0x28: Link status, direction, and network

D.16 PLink status and network: 0x40 .. 0x47

These registers contain status information and the network number that each processor-link belongs to.

Bits	Perm	Init	Description
31:26	RO	-	Reserved
25:24	RO		Identify the SRC_TARGET type 0 - SLink, 1 - PLink, 2 - SSCTL, 3 - Undefine.
23:16	RO		When the link is in use, this is the destination link number to which all packets are sent.
15:6	RO	-	Reserved
5:4	RW	0	Determines the network to which this link belongs, reset as 0.
3	RO	-	Reserved
2	RO		1 when the current packet is considered junk and will be thrown away.
1	RO		1 when the dest side of the link is in use.
0	RO		1 when the source side of the link is in use.

0x40 .. 0x47: PLink status and network

D.17 Link configuration and initialization: 0x80 .. 0x88

These registers contain configuration and debugging information specific to external links. The link speed and width can be set, the link can be initialized, and the link status can be monitored. The registers control links 0..7.

Bits	Perm	Init	Description
31	RW		Write to this bit with '1' will enable the XLink, writing '0' will disable it. This bit controls the muxing of ports with overlapping xlinks.
30	RW	0	0: operate in 2 wire mode; 1: operate in 5 wire mode
29:28	RO	-	Reserved
27	RO		Rx buffer overflow or illegal token encoding received.
26	RO	0	This end of the xlink has issued credit to allow the remote end to transmit
25	RO	0	This end of the xlink has credit to allow it to transmit.
24	WO		Clear this end of the xlink's credit and issue a HELLO token.
23	WO		Reset the receiver. The next symbol that is detected will be the first symbol in a token.
22	RO	-	Reserved
21:11	RW	0	Specify min. number of idle system clocks between two contin- uous symbols witin a transmit token -1.
10:0	RW	0	Specify min. number of idle system clocks between two contin- uous transmit tokens -1.

0x80 .. 0x88: Link configuration and initialization

D.18 Static link configuration: 0xA0 .. 0xA7

These registers are used for static (ie, non-routed) links. When a link is made static, all traffic is forwarded to the designated channel end and no routing is attempted. The registers control links C, D, A, B, G, H, E, and F in that order.

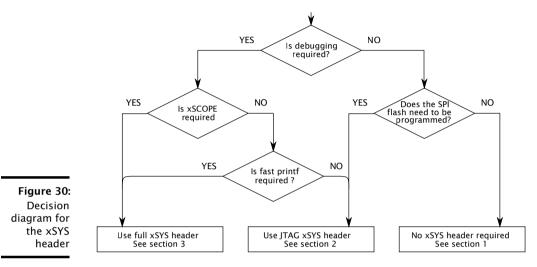
Bits	Perm	Init	Description
31	RW	0	Enable static forwarding.
30:9	RO	-	Reserved
8	RW	0	The destination processor on this node that packets received in static mode are forwarded to.
7:5	RO	-	Reserved
4:0	RW	0	The destination channel end on this node that packets received in static mode are forwarded to.

0xA0 .. 0xA7: Static link configuration



E JTAG, xSCOPE and Debugging

If you intend to design a board that can be used with the XMOS toolchain and xTAG debugger, you will need an xSYS header on your board. Figure 30 shows a decision diagram which explains what type of xSYS connectivity you need. The three subsections below explain the options in detail.



E.1 No xSYS header

The use of an xSYS header is optional, and may not be required for volume production designs. However, the XMOS toolchain expects the xSYS header; if you do not have an xSYS header then you must provide your own method for writing to flash/OTP and for debugging.

E.2 JTAG-only xSYS header

The xSYS header connects to an xTAG debugger, which has a 20-pin 0.1" female IDC header. The design will hence need a male IDC header. We advise to use a boxed header to guard against incorrect plug-ins. If you use a 90 degree angled header, make sure that pins 2, 4, 6, ..., 20 are along the edge of the PCB.

Connect pins 4, 8, 12, 16, 20 of the xSYS header to ground, and then connect:

- ▶ TDI to pin 5 of the xSYS header
- TMS to pin 7 of the xSYS header
- TCK to pin 9 of the xSYS header
- DEBUG_N to pin 11 of the xSYS header

TDO to pin 13 of the xSYS header

The RST_N net should be open-drain, active-low, and have a pull-up to VDDIO.

E.3 Full xSYS header

For a full xSYS header you will need to connect the pins as discussed in Section E.2, and then connect a 2-wire xCONNECT Link to the xSYS header. The links can be found in the Signal description table (Section 4): they are labelled XL0, XL1, etc in the function column. The 2-wire link comprises two inputs and outputs, labelled ${}^{1}_{out}$, ${}^{0}_{out}$, ${}^{0}_{in}$, and ${}^{1}_{in}$. For example, if you choose to use XL0 for xSCOPE I/O, you need to connect up XL0 ${}^{1}_{out}$, XL0 ${}^{0}_{out}$, XL0 ${}^{1}_{in}$, XL0 ${}^{1}_{in}$ as follows:

- XL0¹_{out} (X0D43) to pin 6 of the xSYS header with a 33R series resistor close to the device.
- XL0⁰_{out} (X0D42) to pin 10 of the xSYS header with a 33R series resistor close to the device.
- ▶ XL0⁰_{in} (X0D41) to pin 14 of the xSYS header.
- > XLO_{in}^{1} (X0D40) to pin 18 of the xSYS header.

F Schematics Design Check List

✓ This section is a checklist for use by schematics designers using the XLF232-512-FB374. Each of the following sections contains items to check for each design.

F.1 Power supplies

- □ VDDIO and OTP_VCC supply is within specification before the VDD (core) supply is turned on. Specifically, the VDDIO and OTP_VCC supply is within specification before VDD (core) reaches 0.4V (Section 11).
- The VDD (core) supply ramps monotonically (rises constantly) from 0V to its final value (0.95V 1.05V) within 10ms (Section 11).
- The VDD (core) supply is capable of supplying 1400 mA (Section 11 and Figure 15).
- PLL_AVDD is filtered with a low pass filter, for example an RC filter, see Section 11

F.2 Power supply decoupling

- ☐ The design has multiple decoupling capacitors per supply, for example at least four0402 or 0603 size surface mount capacitors of 100nF in value, per supply (Section 11).
- A bulk decoupling capacitor of at least 10uF is placed on each supply (Section 11).

F.3 Power on reset

The RST_N and TRST_N pins are asserted (low) during or after power up. The device is not used until these resets have taken place.

F.4 Clock

- The CLK input pin is supplied with a clock with monotonic rising edges and low jitter.
- Pins MODE0 and MODE1 are set to the correct value for the chosen oscillator frequency. The MODE settings are shown in the Oscillator section, Section 7. If you have a choice between two values, choose the value with the highest multiplier ratio since that will boot faster.

F.5 Boot

- \square X0D01 has a 1K pull-up to VDDIO (Section 8).
- The device is kept in reset for at least 1 ms after VDDIO has reached its minimum level (Section 8).

F.6 JTAG, XScope, and debugging

- \Box You have decided as to whether you need an XSYS header or not (Section E)
- ☐ If you have not included an XSYS header, you have devised a method to program the SPI-flash or OTP (Section E).

F.7 GPIO

- \Box You have not mapped both inputs and outputs to the same multi-bit port.
- Pins X0D04, X0D05, X0D06, and X0D07 are output only and are, during and after reset, pulled low or not connected (Section 8)
- Pins X2D04, X2D05, X2D06 and X2D07 are output only and during and after reset, X2D06 is pulled high and X2D04, X2D05, and X2D07 are pulled low (Section 8)

F.8 Multi device designs

Skip this section if your design only includes a single XMOS device.

- \Box One device is connected to a QSPI or SPI flash for booting.
- Devices that boot from link have, for example, X0D06 pulled high and have link XL0 connected to a device to boot from (Section 8).

G PCB Layout Design Check List

✓ This section is a checklist for use by PCB designers using the XS2-LF32A-512-FB374. Each of the following sections contains items to check for each design.

G.1 Ground Plane

- Each ground ball has a via to minimize impedance and conduct heat away from the device. (Section 11.2)
- □ Other than ground vias, there are no (or only a few) vias underneath or closely around the device. This create a good, solid, ground plane.

G.2 Power supply decoupling

- The decoupling capacitors are all placed close to a supply pin (Section 11).
- \Box The decoupling capacitors are spaced around the device (Section 11).
- The ground side of each decoupling capacitor has a direct path back to the center ground of the device.

G.3 PLL_AVDD

The PLL_AVDD filter (especially the capacitor) is placed close to the PLL_AVDD pin (Section 11).

H Associated Design Documentation

Document Title	Information	Document Number
Estimating Power Consumption For XS1-LF Devices	Power consumption	X4271
Programming XC on XMOS Devices	Timers, ports, clocks, cores and channels	X9577
xTIMEcomposer User Guide	Compilers, assembler and linker/mapper	X3766
	Timing analyzer, xScope, debugger	
	Flash and OTP programming utilities	

I Related Documentation

Document Title	Information	Document Number
The XMOS XS1 Architecture	ISA manual	X7879
XS1 Port I/O Timing	Port timings	X5821
xCONNECT Architecture	Link, switch and system information	X4249
XS1-LF Link Performance and Design Guidelines	Link timings	X2999
XS1-LF Clock Frequency Control	Advanced clock control	X1433
XS1-L Active Power Conservation	Low-power mode during idle	X7411

XS2-LF32A-512-FB374

J Revision History

Date	Description
2015-03-20	Preliminary release
2015-04-14	Added RST to pins to be pulled hard, and removed reference to TCK from Errata
	Removed TRST_N references in packages that have no TRST_N
	New diagram for boot from embedded flash showing ports
	Pull up requirements for shared clock and external resistor for QSPI
2015-05-06	Removed references to DEBUG_N
2015-07-09	Updated electrical characteristics - Section 12
2015-08-27	Updated part marking and product code - Section 14
2015-11-23	Updated status of X2D04, X2D05, X2D06, X2D07 during boot - Section 8
	Updated Schematics Design Checklist: GPIO for X2D04, X2D05, X2D06, X2D07 during boot - Section F
2015-12-18	Clarified connectivity of internal and external xCONNECT links - Sections 3 and 4
	Made pin names canonical - Sections 3 and 4
	Updated JTAG diagram - Section 10
	Removed references to 400MHz parts - Section 12
2016-01-05	Updated signal tables to use VDDIO - Section 4
	Updated IDD value - Section 12
	Updated land pattern description - Section 11.1
2016-04-20	Typical internal pull-up and pull down current diagrams added - Section 12

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